SSD1619A

Product Preview

400 Source x 300 Gate Red/Black/White
Active Matrix EPD Display Driver with Controller

SOLOMON SYSTECH

Appendix: IC Revision history of SSD1619A Specification

Version	Change Items	Effective Date
0.10	1st Release	29-Dec-16

CONTENTS

TABLES

FIGURES

1 General Description

The SSD1619A is an Active Matrix EPD Display Driver with Controller which can support Red/Black/White. It consists of 400 source outputs, 300 gate outputs, 1 VCOM and 1 VBD for border that can support a maximum display resolution 400x300. In addition, the SSD1619A has a cascade mode that can support higher display resolution.

The SSD1619A embeds booster, regulators and oscillator. Data/Commands are sent from general MCU through the hardware selectable Serial peripheral.

2 Features

- Design for dot matrix type active matrix EPD display
- Support Red/Black/White mono color
- Resolution: 400 source outputs; 300 gate outputs; 1 VCOM; 1VBD for border.
- Power supply:
  - VCI: 2.2 to 3.7V
  - VDDIO: Connect to VCI
  - VDD: 1.8V, regulate from VCI supply
- On chip display RAM
  - Mono B/W: 400x300 bits
  - Mono Red: 400x300 bits
- On-chip booster and regulator for generating VCOM, Gate and Source driving voltage.
- Gate driving output voltage:
  - 2 levels output (VGH, VGL).
  - Max 40Vp-p.
  - VGH: 10V to 20V; VGL: -VGH.
  - Voltage adjustment step: 500mV.
- Source / VBD driving output voltage:
  - 4 levels output (VSH1, VSS, VSL, and VSH2).
    - VSH1/VSH2: 2.4V to 17V (Voltage step: 100mV for 2.4V to 8.8V, 200mV for 8.8V to 17V.)
    - VSL: -9V to -17V (Voltage step: 500mV)
- VCOM output voltage

DCVCOM	ACVCOM
• -3V to -0.2V in 100mV resolution	• 3 levels output ➢ VSH1+DCVCOM ➢ DCVCOM ➢ VSL+DCVCOM

- Built in VCOM sensing
- Support internal generation of OTP programming voltage
- On-chip oscillator.
- Programmable output waveform for different types of EPD display:
  - 28 phases (4 phases/group, 7 groups with repeat function)
  - 1 to 256 times for repeat count
  - Max. 255 frame/phase
- On-chip OTP can store Waveform Setting (max. 25 sets) including (LUT, gate/source voltage, frame rate and Temperature Range), VCOM value and waveform version ID
- Reserve 10-byte OTP space for module identification
- Adjustable frame rate from 15Hz to 200Hz (Remark: For Gate setting as 300 MUX)
- Low voltage detect for supply voltage
- High voltage ready detect for driving voltage
- Read OTP function
- Built-in CRC checking method for waveform setting and temperature range in OTP.
- Support display partial update
- Auto write RAM command for regular pattern
- I2C Single Master Interface to read external temperature sensor reading.
- Internal Temperature Sensor
- Cascade mode to support higher display resolution.
- MCU interface: Serial peripheral.
- Maximum SPI write speed 20MHz
- Available in COG package

3 ORDERING INFORMATION

Table 3-1 : Ordering Information

Ordering Part Number	Package Form	Remark
SSD1619AZ	Gold Bump Die	Bump Face Up On Waffle pack Die thickness: 300um Bump height: 12um

4 Block Diagram

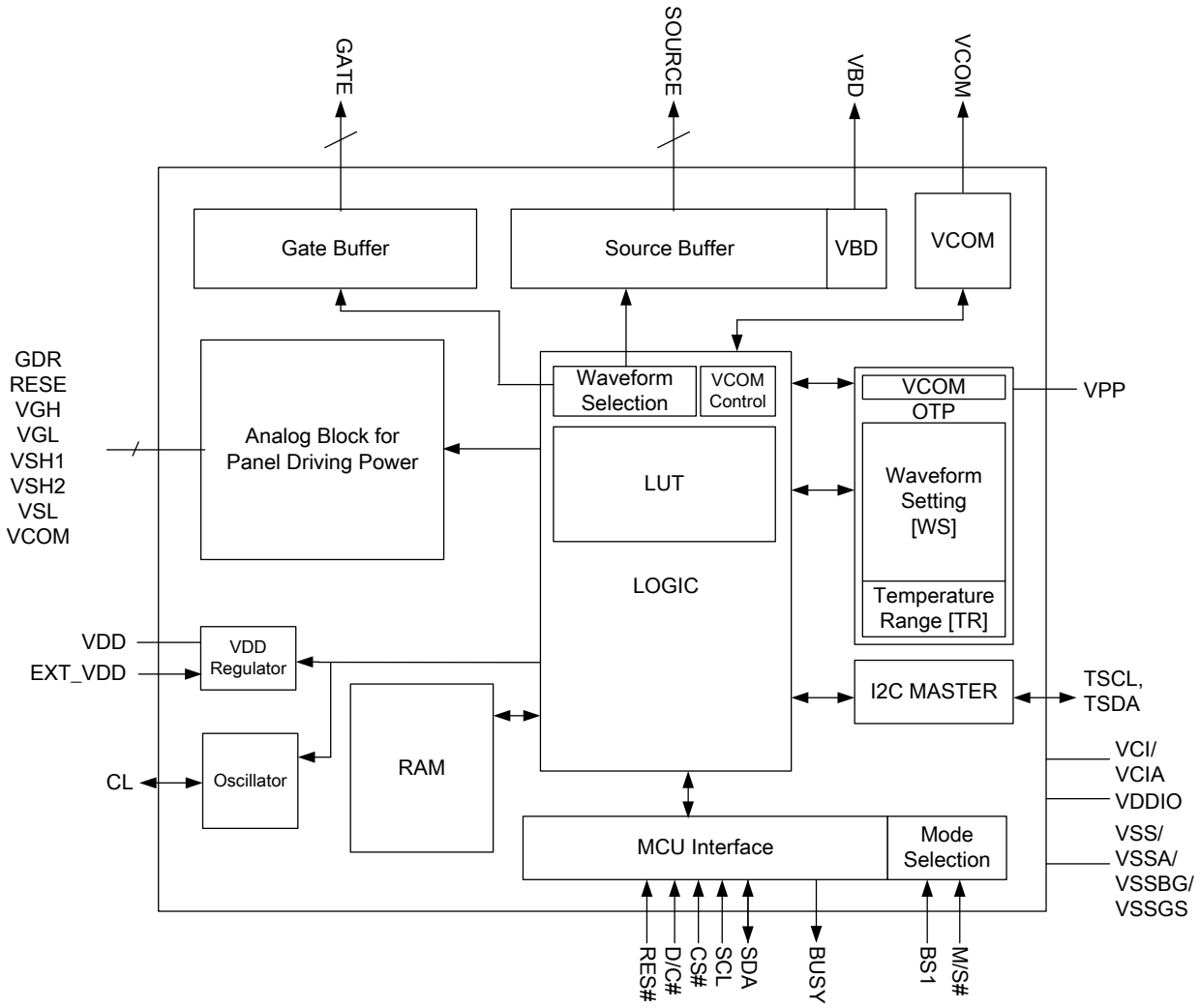


Figure 4-1 : SSD1619A Block Diagram

5 PIN DESCRIPTION

Key: I = Input, O =Output, IO = Bi-directional (input/output), P = Power pin, C = Capacitor Pin
NC = Not Connected, Pull L =connect to V_{SS}, Pull H = connect to V_{DDIO}

Pin name	Type	Connect to	Function	Description	When not in use
Input power					
VCI	P	Power Supply	Power Supply	Power input pin for the chip.	-
VCIA	P	Power Supply	Power Supply	Power input pin for the chip. - Connect to VCI in the application circuit.	-
VDDIO	P	Power Supply	Power for interface logic pins	Power input pin for the Interface. - Connect to VCI in the application circuit.	-
VDD	P	Capacitor	Regulator output	Core logic power pin VDD can be regulated internally from VCI. - For the single chip application, a capacitor should be connected between VDD and VSS under all circumstances. - For the cascade mode application, a capacitor should be connected between VDD and VSS in the master chip under all circumstances. For the slave chip, the capacitor is not necessary as VDD will be supplied from the cascade master chip externally.	-
EXTVDD	I	VDDIO/ VSS	Regulator bypass	This pin is VDD regulator bypass pin. For the single chip application, EXTVDD should be connected to VSS in the application circuit. - For the cascade mode application, EXTVDD of the master chip should be connected to VSS while EXTVDD of the slave chip should be connected to VDDIO in the application circuit.	-
VSS	P	VSS	GND	Ground (Digital).	-
VSSA	P	VSS	GND	Ground (Analog) - Connect to VSS in the application circuit.	-
VSSBG	P	VSS	GND	Ground (Reference) pin. - Connect to VSS in the application circuit.	-
VSSGS	P	VSS	GND	Ground (Output) pin. - Connect to VSS in the application circuit.	-
VPP	P	Power Supply	OTP power	Power Supply for OTP Programming.	Open
Digital I/O					
SCL	I	MPU	Data Bus	Serial clock pin for interface: Refer to Session 6.1 - MCU Interface.	-
SDA	I/O	MPU	Data Bus	Serial data pin for interface: Refer to Session 6.1 - MCU Interface.	
CS#	I	MPU	Logic Control	This pin is the chip select input connecting to the MCU. Refer to Session 6.1 - MCU Interface.	VDDIO or VSS
D/C#	I	MPU	Logic Control	This pin is Data/Command control pin connecting to the MCU. Refer to Session 6.1- MCU Interface.	VDDIO or VSS
RES#	I	MPU	System Reset	This pin is reset signal input. Active Low.	-

<table>
<tr><th>Pin name</th><th>Type</th><th>Connect to</th><th>Function</th><th>Description</th><th>When not in use</th></tr>
<tr><td></td><td></td><td></td><td></td><td></td><td></td></tr>
<tr><td>BUSY</td><td>O</td><td>MPU</td><td>Device Busy Signal</td><td>This pin is Busy state output pin
When Busy is High, the operation of the chip should not be interrupted, and command should not be sent.
For example., The chip would put Busy pin High when
- Outputting display waveform; or
- Programming with OTP
- Communicating with digital temperature sensor

In the cascade mode, the BUSY pin of the slave chip should be left open.</td><td>Open</td></tr>
<tr><td>M/S#</td><td>I</td><td>VDDIO/VSS</td><td>Cascade Mode Selection</td><td>This pin is Master and Slave selection pin.
- For the single chip application, the M/S# pin should be connected to VDDIO.
- In the cascade mode:
For Master Chip, the M/S# pin should be connected to VDDIO.
For Slave Chip, the M/S# pin should be connected to VSS. The oscillator and the booster & regulator circuits of the slave chip will be disabled. The corresponding pins including CL, VDD, VDDIO, VGH, VGL, VSH1, VSH2, VSL and VCOM must be connected to the master chip.</td><td>-</td></tr>
<tr><td>CL</td><td>I/O</td><td>NC</td><td>Clock signal</td><td>This is the clock signal pin.
- For the single chip application, the CL pin should be left open.
- In the cascade mode, the CL pin of the slave chip should be connected to the CL pin of the master chip.</td><td>Open</td></tr>
<tr><td>BS1</td><td>I</td><td>VDDIO/VSS</td><td>MCU Interface Mode Selection</td><td>These pins are for selecting different bus interface.
Table 5-1 : MCU interface selection<table><tr><td>BS1</td><td>MCU Interface</td></tr><tr><td>L</td><td>4-wire SPI</td></tr><tr><td>H</td><td>3-wire SPI (9 bits SPI)</td></tr></table></td><td>-</td></tr>
<tr><td>TSDA</td><td>I/O</td><td>Temperature sensor SDA</td><td>Interface to Digital Temp. Sensor</td><td>This pin is I²C Interface to digital temperature sensor Data pin.
External pull up resistor is required when connecting to I²C slave.</td><td>Open</td></tr>
<tr><td>TSCL</td><td>O</td><td>Temperature sensor SCL</td><td>Interface to Digital Temp. Sensor</td><td>This pin is I²C Interface to digital temperature sensor Clock pin.
External pull up resistor is required when connecting to I²C slave.</td><td>Open</td></tr>
<tr><td colspan="6">Analog Pin</td></tr>
<tr><td>GDR</td><td>O</td><td>POWER MOSFET Driver Control</td><td rowspan="4">VGH, VGL Generation</td><td>N-Channel MOSFET gate drive control pin.</td><td>-</td></tr>
<tr><td>RESE</td><td>I</td><td>Booster Control Input</td><td>Current sense input pin for the control Loop.</td><td>-</td></tr>
<tr><td>VGH</td><td>C</td><td>Stabilizing capacitor</td><td>Positive Gate driving voltage.
Connect a stabilizing capacitor between VGH and VSS in the application circuit.</td><td>-</td></tr>
<tr><td>VGL</td><td>C</td><td>Stabilizing capacitor</td><td>This pin is Negative Gate driving voltage.
Connect a stabilizing capacitor between VGL and VSS in the application circuit.</td><td>-</td></tr>
</table>

Pin name	Type	Connect to	Function	Description	When not in use
VSH1	C	Stabilizing capacitor	VSH1, VSH2, VSL Generation	This pin is Positive Source driving voltage, VSH1 Connect a stabilizing capacitor between VSH1 and VSS in the application circuit.	-
VSH2	C	Stabilizing capacitor		This pin is Positive Source driving voltage, VSH2 Connect a stabilizing capacitor between VSH2 and VSS in the application circuit.	
VSL	C	Stabilizing capacitor		This pin is Negative Source driving voltage. Connect a stabilizing capacitor between VSL and VSS in the application circuit.	-
VCOM	C	Panel/ Stabilizing capacitor	VCOM Generation	These pins are VCOM driving voltage Connect a stabilizing capacitor between VCOM and VSS in the application circuit.	-
Panel Driving					
S [399:0]	O	Panel	Source driving signal	Source output pin.	Open
G [299:0]	O	Panel	Gate driving signal	Gate output pin.	Open
VBD	O	Panel	Border driving signal	Border output pin.	Open
Others					
NC	NC	NC	Not Connected	Keep open. Don’t connect with other NC pins.	Open
RSV	NC	NC	Reserved	This is a reserved pin, keep floating	Open
TPA, TPB, TPC, TPD, TPF, FB	NC	NC	Reserved for Testing	Reserved pins. - Keep open. - Don’t connect to other NC pins and test pins including TPA, TPB, TPC, TPD, TPE, TPF and FB.	Open
GD [3:0]	O	NC	Not Connected	Reserved pins. - Keep open.	Open
TIN	I	NC	Reserved for Testing	Reserved pins. - Keep open.	Open
TPE	O	NC			Open

6 Functional Block Description

6.1 MCU Interface

6.1.1 MCU Interface selection

The SSD1619A can support 3-wire/4-wire serial peripheral. In the SSD1619A, the MCU interface is pin selectable by BS1 shown in Table 6-1.

Note
(1) L is connected to V_{SS}
(2) H is connected to V_{DDIO}

Table 6-1 : Interface pins assignment under different MCU interface

MCU Interface	Pin Name					
	BS1	**RES#**	**CS#**	**D/C#**	**SCL**	**SDA**
4-wire serial peripheral interface (SPI)	Connect to VSS	Required	Required	Required	SCL	SDA
3-wire serial peripheral interface (SPI) – 9 bits SPI	Connect to VDDIO	Required	Required	Connect to VSS	SCL	SDA

6.1.2 MCU Serial Interface (4-wire SPI)

The 4-wire SPI consists of serial clock SCL, serial data SDA, D/C# and CS#. The control pins status in 4-wire SPI in writing command/data is shown in Table 6-2 and the write procedure 4-wire SPI is shown in Table 6-2

Table 6-2 : Control pins status of 4-wire SPI

Function	SCL pin	SDA pin	D/C# pin	CS# pin
Write command	↑	Command bit	L	L
Write data	↑	Data bit	H	L

Note:
(1) L is connected to V_{SS} and H is connected to V_{DDIO}
(2) ↑ stands for rising edge of signal
(3) SDA(Write Mode) is shifted into an 8-bit shift register on every rising edge of SCL in the order of D7, D6, ... D0. The level of D/C# should be kept over the whole byte. The data byte in the shift register is written to the Graphic Display Data RAM (RAM)/Data Byte register or command Byte register according to D/C# pin.

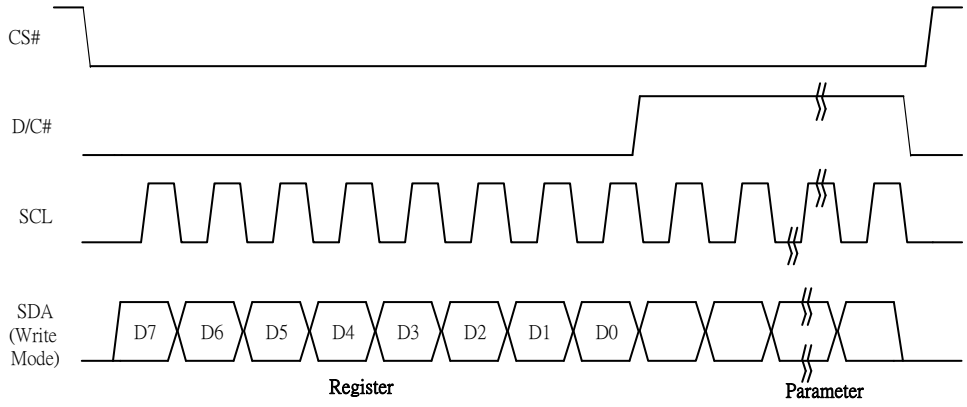


Figure 6-1 : Write procedure in 4-wire SPI mode

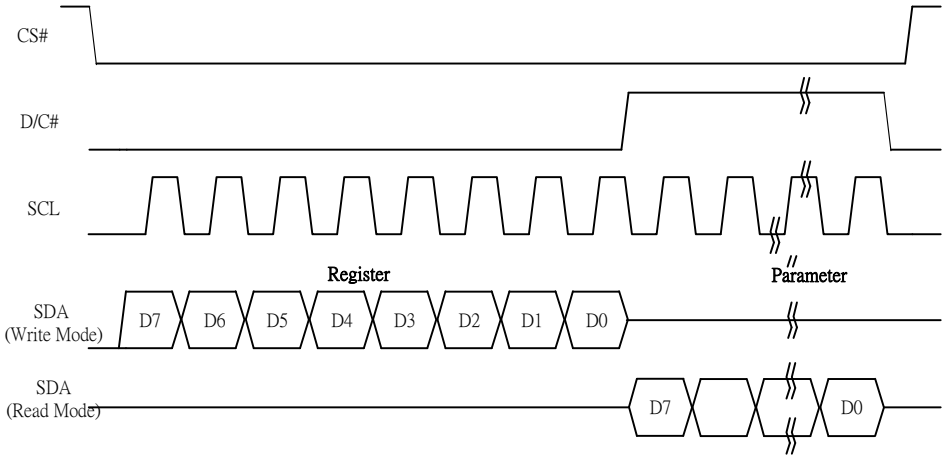


Figure 6-2 : Read procedure in 4-wire SPI mode

6.1.3 MCU Serial Peripheral Interface (3-wire SPI)

The 3-wire SPI consists of serial clock SCL, serial data SDA and CS#. The operation is similar to 4-wire SPI while D/C# pin is not used and it must be tied to LOW. The control pins status in 3-wire SPI is shown in Table 6-3.

In the write operation, a 9-bit data will be shifted into the shift register on every clock rising edge. The bit shifting sequence is D/C# bit, D7 bit, D6 bit to D0 bit. The first bit is D/C# bit which determines the following byte is command or write data. When D/C# bit is 0, the following byte is command. When D/C# bit is 1, the following byte is data. Table 6-3 shows the write procedure in 3-wire SPI

Table 6-3 : Control pins status of 3-wire SPI

Function	SCL pin	SDA pin	D/C# pin	CS# pin
Write command	↑	Command bit	Tie LOW	L
Write data	↑	Data bit	Tie LOW	L

Note:

(1) L is connected to V_{SS} and H is connected to V_{DDIO}

(2) ↑ stands for rising edge of signal

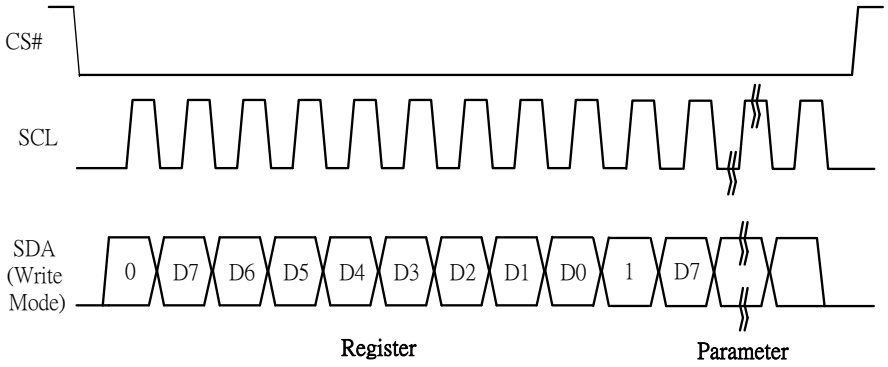


Figure 6-3 : Write procedure in 3-wire SPI

In the read operation (Register 0x1B, 0x27, 0x2D, 0x2E, 0x2F, 0x35), SDA data are transferred in the unit of 9 bits. After CS# pull low, the first byte is command byte, the D/C# bit is as 0 and following with the register byte. After command byte send, the following byte(s) are data byte(s), with D/C# bit is 1. After D/C# bit sending from MCU, an 8-bit data will be shifted out on every clock falling edge. The serial data SDA bit shifting sequence is D7, D6, to D0 bit. Figure 6-4 shows the read procedure in 3-wire SPI.

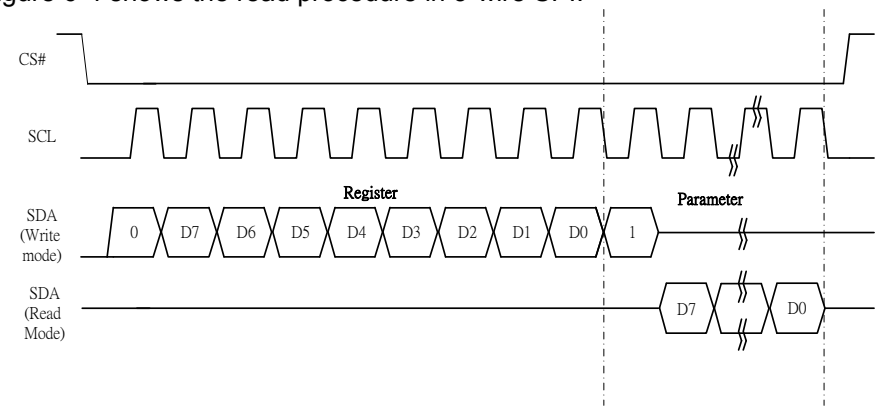


Figure 6-4 : Read procedure in 3-wire SPI mode

6.2 RAM

The On chip display RAM is holding the image data.
1 set of RAM is built for Mono B/W. The RAM size is 400x300 bits.
1 set of RAM is built for Mono Red. The RAM size is 400x300 bits.

Table 6-4 : LUT mapping to RAM content for Mono Black White and Mono Red

R	B/W	LUT
0	0	LUT 0
0	1	LUT 1
1	0	LUT 2
1	1	LUT 3

In order to write the image data into the display RAM, it is necessary to define the Data Entry Mode Setting (Command 0x11h), the Driver Output Control (Command 0x01h) and the Gate Scan Start Position (Command 0x0Fh). The following is an example to show how to set these commands. And, Table 6-5 is the corresponding RAM address mapping of these command settings.

- Command “Data Entry Mode Setting” R11h is set to:

Address Counter update in X direction	AM=0
X: Increment Y: Increment	ID[1:0] =11

- Command “Driver Output Control” R01h is set to:

300 Mux		MUX = 12Bh
Select G0 as 1st gate		GD = 0
Left and Right gate Interlaced		SM = 0
Scan From G0 to G299		TB = 0

- Command “Gate Scan Start Position” R0Fh is set to:

Set the Start Position of Gate = G0	SCN=0

- Then the data byte sequence: DB0, DB1, DB2 … DB18 … DB19, DB20 … DB14999

Table 6-5 : RAM address map according to above condition

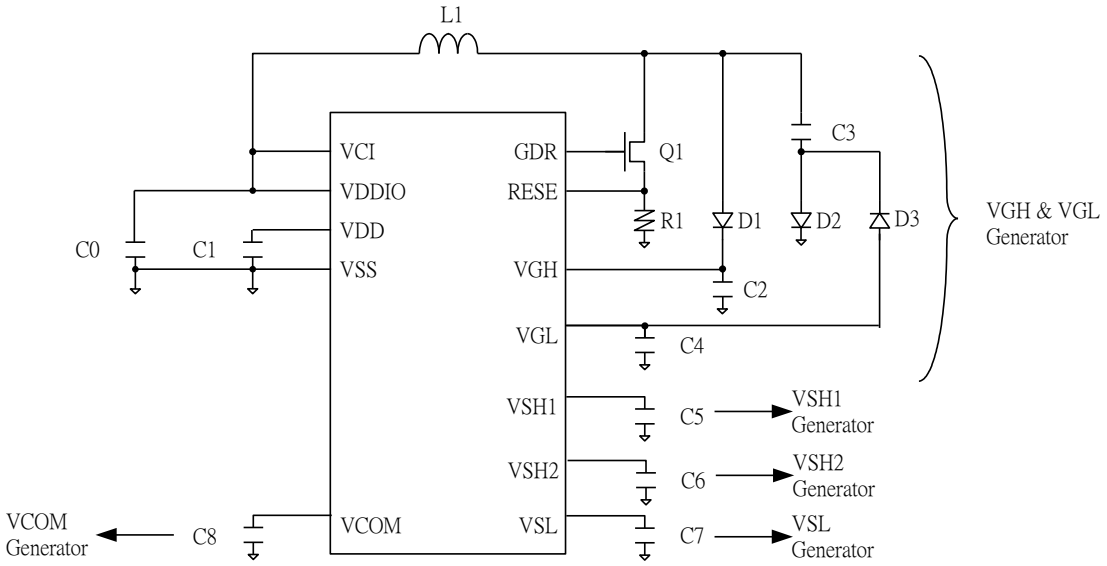
		S0	S1	S2	S3	S4	S5	S6	S7	…	…	S392	S393	S394	S395	S396	S397	S398	S399	Source X-ADDR
		00h								…		31h								
G0	00h	DB0 [7]	DB0 [6]	DB0 [5]	DB0 [4]	DB0 [3]	DB0 [2]	DB0 [1]	DB0 [0]	…	…	DB49 [7]	DB49 [6]	DB49 [5]	DB49 [4]	DB49 [3]	DB49 [2]	DB49 [1]	DB49 [0]	
G1	01h	DB50 [7]	DB50 [6]	DB50 [5]	DB50 [4]	DB50 [3]	DB50 [2]	DB50 [1]	DB50 [0]	…	…	DB99 [7]	DB99 [6]	DB99 [5]	DB99 [4]	DB99 [3]	DB99 [2]	DB99 [1]	DB99 [0]	
…	…	…	…	…	…	…	…	…	…	…	…	…	…	…	…	…	…	…	…	
…	…	…	…	…	…	…	…	…	…	…	…	…	…	…	…	…	…	…	…	
…	…	…	…	…	…	…	…	…	…	…	…	…	…	…	…	…	…	…	…	
G298	12Ah	DB14900 [7]	DB14900 [6]	DB14900 [5]	DB14900 [4]	DB14900 [3]	DB14900 [2]	DB14900 [1]	DB14900 [0]	…	…	DB14949 [7]	DB14949 [6]	DB14949 [5]	DB14949 [4]	DB14949 [3]	DB14949 [2]	DB14949 [1]	DB14949 [0]	
G299	12Bh	DB14950 [7]	DB14950 [6]	DB14950 [5]	DB14950 [4]	DB14950 [3]	DB14950 [2]	DB14950 [1]	DB14950 [0]	…	…	DB14999 [7]	DB14999 [6]	DB14999 [5]	DB14999 [4]	DB14999 [3]	DB14999 [2]	DB14999 [1]	DB14999 [0]	
GATE	Y-ADDR																			

6.3 Oscillator

The oscillator module generates the clock reference for waveform timing and analog operations.

6.4 Booster & Regulator

A voltage generation system is included in the driver. It provides all necessary driving voltages required for an AMEPD panel including VGH, VGL, VSH1, VSH2, VSL and VCOM. External application circuit is needed to make the on-chip booster & regulator circuit work properly.



6.5 VCOM Sensing

该功能块提供了选择最佳 VCOM DC 电平的方案。 感测值可以编程到 OTP 中。

This functional block provides the scheme to select the optimal VCOM DC level. The sensed value can be programmed into OTP.

The flow of VCOM sensing: VCOM感测流程：

- Active Gate is scanning during the VCOM sense Period. 主动门在 VCOM 检测期间进行扫描。
- Source are VSS. 来源是VSS
- VCOM pin used for sensing. VCOM 引脚用于感测。
- During Sensing period, BUSY is high. 在检测期间，BUSY 为高电平。
- After Sensing, Active Gate return to non-select stage.
  感应后，有源门返回非选择阶段。

栅极波形、可编程源和 VCOM 波形

6.6 Gate waveform, Programmable Source and VCOM waveform

共7组，每组4相，共28相，用于不同相长的可编程源波形。`

- There are 7 groups, each group contains 4 phases, totally 28 phases for programmable Source waveform with different phase length.
- The phase length of LUT0~LUT4 is defined as TP[nX] LUT0~LUT4的相位长度定义为TP[nX]
  - The range of TP[nX] is from 0 to 255. TP[nX] 的范围是从 0 到 255。 n 表示从 0 到 6 的组号，X 表示从 A 到 D 的子组编号。
  - n represents the Group number from 0 to 6; X represents the sub-group number from A to D.
  - TP[nX] = 0 indicates phase skipped. TP[nX] = 0 表示跳相。
- The repeat count of group is defined as RP[n], which is used for the count of repeating TP[nA] , TP[nB], TP[nC] and TP[nD]; 组的重复计数定义为RP[n]，用于重复TP[nA]、TP[nB]、TP[nC]和TP[nD]的计数；
  - The range of RP[n] is from 0 to 255. RP[n] 的范围是从 0 到 255。
  - n represents the Group number from 0 to 6; n 表示从 0 到 6 的组号；`
  - RP[n] = 0 indicates run time =1, RP[n] = 0 表示运行时间 =1，
- Source/VCOM Voltage Level: VS [nX-LUT] is constant in each phase. 源/VCOM 电压电平：VS [nX-LUT] 在每个相位中是恒定的。
- VS [nX-LUTn] indicates the voltage in phase n for transition LUT.
  - 00 – VSS VS [nX-LUTn]表示过渡LUT的n相电压。
  - 01 – VSH1
  - 10 – VSL
  - 11 – VSH2

Table 6-6 : VS [nX-LUTn] value mapping table

LUT0	B	00 – VSS, 01 – VSH1, 10 – VSL, 11-VSH2
LUT1	W	00 – VSS, 01 – VSH1, 10 – VSL, 11-VSH2
LUT2	R	00 – VSS, 01 – VSH1, 10 – VSL, 11-VSH2
LUT3	R	Assign as the same as LUT2
LUT4	VCOM	00 –DCVCOM, 01 – VSH1+DCVCOM, 10 – VSL+ DCVCOM

- VS [nX-LUT], TP[nX], RP[n], VSH , VSL are stored in waveform lookup table register [LUT].

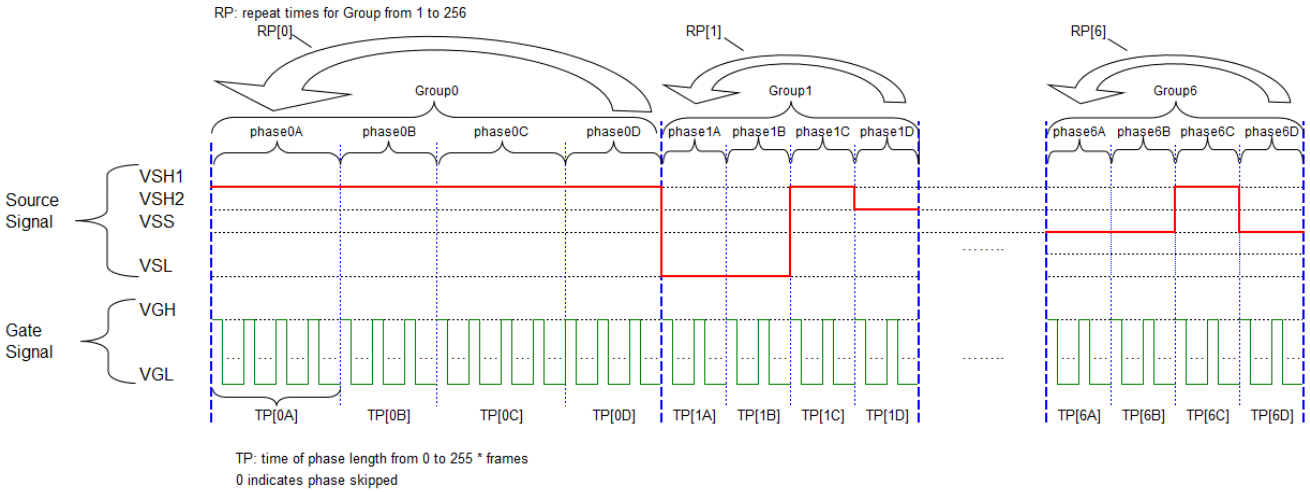


Figure 6-5 : Gate waveform and Programmable Source and VCOM waveform illustration

6.7 Waveform Setting 波形设定

WAVEFORM SETTING (WS) 包含 76 个字节，用于定义显示驱动波形设置。它们按以下格式排列

WAVEFORM SETTING (WS) contains 76bytes, which define the display driving waveform settings. They are arranged in following format figure shown

	D7	D6	D5	D4	D3	D2	D1	D0
0	VS[0A-L0]		VS[0B-L0]		VS[0C-L0]		VS[0D-L0]	
1	VS[1A-L0]		VS[1B-L0]		VS[1C-L0]		VS[1D-L0]	
2	VS[2A-L0]		VS[2B-L0]		VS[2C-L0]		VS[2D-L0]	
3	VS[3A-L0]		VS[3B-L0]		VS[3C-L0]		VS[3D-L0]	
4	VS[4A-L0]		VS[4B-L0]		VS[4C-L0]		VS[4D-L0]	
5	VS[5A-L0]		VS[5B-L0]		VS[5C-L0]		VS[5D-L0]	
6	VS[6A-L0]		VS[6B-L0]		VS[6C-L0]		VS[6D-L0]	
7	VS[0A-L1]		VS[0B-L1]		VS[0C-L1]		VS[0D-L1]	
…								
…								
31	VS[3A-L4]		VS[3B-L4]		VS[3C-L4]		VS[3D-L4]	
32	VS[4A-L4]		VS[4B-L4]		VS[4C-L4]		VS[4D-L4]	
33	VS[5A-L4]		VS[5B-L4]		VS[5C-L4]		VS[5D-L4]	
34	VS[6A-L4]		VS[6B-L4]		VS[6C-L4]		VS[6D-L4]	
35	TP[0A]							
36	TP[0B]							
37	TP[0C]							
38	TP[0D]							
39	RP[0]							
40	TP[1A]							
41	TP[1B]							
42	TP[1C]							
43	TP[1D]							
44	RP[1]							
…	…							
…	…							
65	TP[6A]							
66	TP[6B]							
67	TP[6C]							
68	TP[6D]							
69	RP[6]							
70	VGH							
71	VSH1							
72	VSH2							
73	VSL							
74	Frame 1							
75	Frame 2							

Figure 6-6 : VS[nX-LUT] and TP[n] mapping in LUT

WS can be accessed by MCU interface or loaded from OTP.
5 registers are involved to set WS from MCU interface

- WS byte 0~69, the content of VS [n-XY], TP [n#], RP[n], are the parameter belonging to Register 0x32
- WS byte 70, the content of gate level, is the parameter belonging to Register 0x03.
- WS byte 71~73, the content of source level, is the parameter belonging to Register 0x04.
- WS byte 74, the content of dummy line, is the parameter belonging to Register 0x3A.
- WS byte 75, the content of gate line width, is the parameter belonging to Register 0x3B.

6.8 OTP

6.8.1 The OTP information

OTP 是非易失性存储器，存储以下信息：

The OTP is the non-volatile memory and stored the information of: 25组WAVEFORM SETTING (WS)，包括（LUT、栅极/源极电压和帧率）

- 25 set of WAVEFORM SETTING (WS), including (LUT, gate/source voltage and frame rate)
- 25 set of TEMPERATURE RANGE (TR). which consist of 25组温度范围（TR）。 其中包括
  - Lower limit (TEMP [m-L]) and Upper limit (TEMP [m-H]) for each set of WS#. 每组 WS# 的下限（TEMP [m-L]）和上限（TEMP [m-H]）
- VCOM value. VCOM 值
- Waveform version ID 波形版本 ID

Remark: WS [m]表示温度组m的波形设置，配置同LUT中的定义。WS[m] 对应的低温范围定义为 TEMP [m-L] 和高温范围定义为 TEMP [m-H]

- WS [m] means the waveform setting of temperature set m, the configuration are same as the definition in LUT. The corresponding low temperature range of WS[m] defined as TEMP [m-L] and high range defined as TEMP [m-H]
- Load WS [m] from OTP for LUT if Temp [m-L] < Temperature Register <= Temp [m-H] 如果 Temp [m-L] < 温度寄存器 <= Temp [m-H] 从 LUT 的 OTP 加载 WS [m]

6.8.2 The OTP content and address mapping

The mapping table of OTP for waveform setting and temperature range is shown in Figure 6-7：

OTP 波形设定与温度范围对应表如图 6-7 所示：

	D7	D6	D5	D4	D3	D2	D1	D0	
0	WS 0								
…									
75									
76	WS 1								
…									
151									
152	WS 2								
…									
227									
228	WS 3								
…									
303									
	…								
1748	WS 23								
…									
1823									
1824	WS 24								
…									
1899									
1900	temp_L[7:0]								
1901	temp_H[3:0]				temp_L[11:8]				TR0
1902	temp_H[11:4]								
1903	TR1								
1904									
1905									
1906	TR2								
1907									
1908									
1909	TR3								
1910									
1911									
1912	TR4								
1913									
1914									
	…								
1969	TR23								
1970									
1971									
1972	TR24								
1973									
1974									

Figure 6-7：The Waveform setting mapping in OTP for waveform setting and temperature range

6.9 Temperature Searching Mechanism

Legend:

WS#	Waveform Setting no. #
TR#	Temperature Range no. #
LUT	560 bit register storing the waveform setting (volatile)
Temperature register	12bit Register storing reading from temperature sensor (volatile)
OTP	A non-volatile storing 25 sets of waveform setting and 25 set of temperature range
WS_sel_ address	an address pointer indicating the selected WS#

OTP (non-volatile)	
WS0	TR0
WS1	TR1
WS2	TR2
WS3	TR3
…	…
WS23	TR23
WS24	TR24

Figure 6-8 : Waveform Setting and Temperature Range # mapping

IC implementation requirement

1 Compare temperature register from **TR0 to TR24**, in sequence. **The last match will be recorded**

i.e. If the temperature register fall in both TR3 and TR5. WS5 will be selected

2 There is no restriction on the sequence of TR0, TR2…. TR24

Example Temperature Range assignment

Waveform setting	Temperature range	Lower Limit [Hex]	Upper Limit[Hex]
WS0	-128 DegC < Temperature <= 5 DegC	800	050
WS1	5 DegC < Temperature <= 10DegC	050	0A0
WS2	10 DegC < Temperature <= 15DegC	0A0	0F0
WS3	15 DegC < Temperature <= 20DegC	0F0	140
WS4	20 DegC < Temperature <= 25DegC	140	190
WS5	25 DegC < Temperature <= 30DegC	190	1E0
WS6	30 DegC < Temperature <= 35DegC	1E0	230
WS7	35 DegC < Temperature <= 127.9DegC	230	7FF
Others		000	000

Figure 6-9 : Example Temperature Range

User application

1 If temperature is 5 DegC, WS0 is selected

2 If temperature is 23 DegC, WS4 is selected

3 If temperature > 35 DegC, WS7 is selected

6.10 External Temperature Sensor I2C Single Master Interface

The chip provides two I/O lines [TSDA and TSCL] for connecting digital temperature sensor for temperature reading sensing.
TSDA will treat as SDA line and TSCL will treat as SCL line. They are required connecting with external pull-up resistor.

1. If the Temperature value MSByte bit D11 = 0, then
   the temperature is positive and value (DegC) = + (Temperature value) / 16
2. If the Temperature value MSByte bit D11 = 1, then
   the temperature is negative and value (DegC) = - (2's complement of Temperature value) / 16

12-bit binary (2's complement)	Hexadecimal Value	Decimal Value	Value [DegC]
0111 1111 0000	7F0	2032	127
0111 1110 1110	7EE	2030	126.875
0111 1110 0010	7E2	2018	126.125
0111 1101 0000	7D0	2000	125
0001 1001 0000	190	400	25
0000 0000 0010	002	2	0.125
0000 0000 0000	000	0	0
1111 1111 1110	FFE	-2	-0.125
1110 0111 0000	E70	-400	-25
1100 1001 0010	C92	-878	-54.875
1100 1001 0000	C90	-880	-55

6.11 Cascade Mode

The SSD1619A has a cascade mode that can cascade 2 chips to achieve the display resolution up to 800 (sources) x 300 (gates). The pin M/S# is used to configure the chip. When M/S# is connected to VDDIO, the chip is configured as a master chip. When M/S# is connected to VSS, the chip is configured as a slave chip.

When the chip is configured as a master chip, it will be the same as a single chip application, ie, all circuit blocks will be worked as usual. When the chip is configured as a slave chip, its oscillator and booster & regulator circuit will be disabled. The oscillator clock and all booster voltages will be come from the master chip. Therefore, the corresponding pins including CL, VDD, VGH, VGL, VSH1, VSH2, VSL, VGL and VCOM must be connected to the master chip.

6.12 VCI Detection

The VCI detection function is used to detect the VCI level when it is lower than Vlow, threshold voltage set by register.

In the SSD1619A, there is a command to execute the VCI detection function. When the VCI detection command is issued, the VCI detection will be executed. During the detection period, BUSY output is at high level. BUSY output is at low level when the detection is completed. Then, user can issue the Status Bit Read command to check the status bit for the result of VCI, which 0 is normal, 1 is VCI<Vlow.

6.13 HV Ready Detection

The HV Ready detection function is used to detect whether the analog block is ready.

In the SSD1619A, there is a command to execute the HV Ready detection function. When the HV Ready detection command is issued, the HV Ready will be executed. During the detection period, BUSY output is at high level. BUSY output is at low level when the detection is completed. Then, user can issue the Status Bit Read command to check the status bit for the result of HV Ready, which 0 is normal, 1 indicate HV is not ready.

7 COMMAND TABLE

Table 7-1: Command Table

<table>
<tr><th colspan="12">Command Table</th></tr>
<tr><th>R/W#</th><th>D/C#</th><th>Hex</th><th>D7</th><th>D6</th><th>D5</th><th>D4</th><th>D3</th><th>D2</th><th>D1</th><th>D0</th><th>Command</th><th>Description</th></tr>
<tr><td>0</td><td>0</td><td>01</td><td>0</td><td>0</td><td>0</td><td>0</td><td>0</td><td>0</td><td>0</td><td>1</td><td rowspan="4">Driver Output control</td><td rowspan="4">Gate setting
A[8:0]= 12Bh [POR], 300 MUX
MUX Gate lines setting as (A[8:0] + 1).

B[2:0] = 000 [POR].
Gate scanning sequence and direction

B[2]: GD
Selects the 1st output Gate
GD=0 [POR],
G0 is the 1st gate output channel, gate output sequence is G0,G1, G2, G3, …
GD=1,
G1 is the 1st gate output channel, gate output sequence is G1, G0, G3, G2, …

B[1]: SM
Change scanning order of gate driver.
SM=0 [POR],
G0, G1, G2, G3…299 (left and right gate interlaced)
SM=1,
G0, G2, G4 …G298, G1, G3, …G299

B[0]: TB
TB = 0 [POR], scan from G0 to G299
TB = 1, scan from G299 to G0.</td></tr>
<tr><td>0</td><td>1</td><td></td><td>A_7</td><td>A_6</td><td>A_5</td><td>A_4</td><td>A_3</td><td>A_2</td><td>A_1</td><td>A_0</td></tr>
<tr><td>0</td><td>1</td><td></td><td>0</td><td>0</td><td>0</td><td>0</td><td>0</td><td>0</td><td>0</td><td>A_8</td></tr>
<tr><td>0</td><td>1</td><td></td><td>0</td><td>0</td><td>0</td><td>0</td><td>0</td><td>B_2</td><td>B_1</td><td>B_0</td></tr>
<tr><td colspan="13"></td></tr>
<tr><td>0</td><td>0</td><td>03</td><td>0</td><td>0</td><td>0</td><td>0</td><td>0</td><td>0</td><td>1</td><td>1</td><td rowspan="2">Gate Driving voltage Control</td><td rowspan="2">Set Gate driving voltage
A[4:0] = 19h [POR]
VGH setting from 10V to 20V
<table><tr><th>A[4:0]</th><th>VGH</th><th>A[4:0]</th><th>VGH</th></tr><tr><td>03h</td><td>10</td><td>0Fh</td><td>16</td></tr><tr><td>04h</td><td>10.5</td><td>10h</td><td>16.5</td></tr><tr><td>05h</td><td>11</td><td>11h</td><td>17</td></tr><tr><td>06h</td><td>11.5</td><td>12h</td><td>17.5</td></tr><tr><td>07h</td><td>12</td><td>13h</td><td>18</td></tr><tr><td>08h</td><td>12.5</td><td>14h</td><td>18.5</td></tr><tr><td>09h</td><td>13</td><td>15h</td><td>19</td></tr><tr><td>0Ah</td><td>13.5</td><td>16h</td><td>19.5</td></tr><tr><td>0Bh</td><td>14</td><td>17h</td><td>20</td></tr><tr><td>0Ch</td><td>14.5</td><td>Other</td><td>NA</td></tr><tr><td>0Dh</td><td>15</td><td></td><td></td></tr><tr><td>0Eh</td><td>15.5</td><td></td><td></td></tr></table></td></tr>
<tr><td>0</td><td>1</td><td></td><td>0</td><td>0</td><td>0</td><td>A_4</td><td>A_3</td><td>A_2</td><td>A_1</td><td>A_0</td></tr>
</table>

Command Table

R/W#	D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description
0	0	04	0	0	0	0	0	1	0	0	Source Driving voltage Control	Set Source driving voltage A[7:0] = 41h [POR], VSH1 at 15V B[7:0] = A8h [POR], VSH2 at 5V. C[7:0] = 32h [POR], VSL at -15V
0	1		A_7	A_6	A_5	A_4	A_3	A_2	A_1	A_0		
0	1		B_7	B_6	B_5	B_4	B_3	B_2	B_1	B_0		
0	1		C_7	C_6	C_5	C_4	C_3	C_2	C_1	C_0		

A[7]/B[7] = 1,
VSH1/VSH2 voltage setting from 2.4V to 8.8V

A/B[7:0]	VSH1/VSH2	A/B[7:0]	VSH1/VSH2
8Eh	2.4	AFh	5.7
8Fh	2.5	B0h	5.8
90h	2.6	B1h	5.9
91h	2.7	B2h	6
92h	2.8	B3h	6.1
93h	2.9	B4h	6.2
94h	3	B5h	6.3
95h	3.1	B6h	6.4
96h	3.2	B7h	6.5
97h	3.3	B8h	6.6
98h	3.4	B9h	6.7
99h	3.5	BAh	6.8
9Ah	3.6	BBh	6.9
9Bh	3.7	BCh	7
9Ch	3.8	BDh	7.1
9Dh	3.9	BEh	7.2
9Eh	4	BFh	7.3
9Fh	4.1	C0h	7.4
A0h	4.2	C1h	7.5
A1h	4.3	C2h	7.6
A2h	4.4	C3h	7.7
A3h	4.5	C4h	7.8
A4h	4.6	C5h	7.9
A5h	4.7	C6h	8
A6h	4.8	C7h	8.1
A7h	4.9	C8h	8.2
A8h	5	C9h	8.3
A9h	5.1	CAh	8.4
AAh	5.2	CBh	8.5
ABh	5.3	CCh	8.6
ACh	5.4	CDh	8.7
ADh	5.5	CEh	8.8
AEh	5.6	Other	NA

A[7]/B[7] = 0,
VSH1/VSH2 voltage setting from 9V to 17V

A/B[7:0]	VSH1/VSH2	A/B[7:0]	VSH1/VSH2
23h	9	3Ch	14
24h	9.2	3Dh	14.2
25h	9.4	3Eh	14.4
26h	9.6	3Fh	14.6
27h	9.8	40h	14.8
28h	10	41h	15
29h	10.2	42h	15.2
2Ah	10.4	43h	15.4
2Bh	10.6	44h	15.6
2Ch	10.8	45h	15.8
2Dh	11	46h	16
2Eh	11.2	47h	16.2
2Fh	11.4	48h	16.4
30h	11.6	49h	16.6
31h	11.8	4Ah	16.8
32h	12	4Bh	17
33h	12.2	Other	NA
34h	12.4		
35h	12.6		
36h	12.8		
37h	13		
38h	13.2		
39h	13.4		
3Ah	13.6		
3Bh	13.8		

C[7] = 0,
VSL setting from -9V to -17V

C[7:0]	VSL
1Ah	-9
1Ch	-9.5
1Eh	-10
20h	-10.5
22h	-11
24h	-11.5
26h	-12
28h	-12.5
2Ah	-13
2Ch	-13.5
2Eh	-14
30h	-14.5
32h	-15
34h	-15.5
36h	-16
38h	-16.5
3Ah	-17
Other	NA

Command Table

R/W#	D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description
0	0	0C	0	0	0	0	1	1	0	0	Booster Soft start Control	Booster Enable with Phase 1, Phase 2 and Phase 3 for soft start current and duration setting.
0	1		1	A_6	A_5	A_4	A_3	A_2	A_1	A_0		A[7:0] -> Soft start setting for Phase1 = 8Bh [POR]
0	1		1	B_6	B_5	B_4	B_3	B_2	B_1	B_0		B[7:0] -> Soft start setting for Phase2 = 9Ch [POR]
0	1		1	C_6	C_5	C_4	C_3	C_2	C_1	C_0		C[7:0] -> Soft start setting for Phase3 = 96h [POR]
0	1		0	0	D_5	D_4	D_3	D_2	D_1	D_0		D[7:0] -> Duration setting = 0Fh [POR]

Bit Description of each byte:
A[6:0] / B[6:0] / C[6:0]:

Bit[6:4]	Driving Strength Selection 驱动强度选择
000	1(Weakest)
001	2
010	3
011	4
100	5
101	6
110	7
111	8(Strongest)

Bit[3:0]	Min Off Time Setting of GDR [Time unit]
0000 ~ 0011	NA
0100	2.6
0101	3.2
0110	3.9
0111	4.6
1000	5.4
1001	6.3
1010	7.3
1011	8.4
1100	9.8
1101	11.5
1110	13.8
1111	16.5

D[5:0]: duration setting of phase
D[5:4]: duration setting of phase 3
D[3:2]: duration setting of phase 2
D[1:0]: duration setting of phase 1

Bit[1:0]	Duration of Phase [Approximation]
00	10ms
01	20ms
10	30ms
11	40ms

Command Table

R/W#	D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description
0	0	0F	0	0	0	0	1	1	1	1	Gate scan start position	Set the scanning start position of the gate driver. The valid range is from 0 to 299. A[8:0] = 000h [POR] When TB=0: SCN [8:0] = A[8:0] When TB=1: SCN [8:0] = 299 - A[8:0]
0	1		A_7	A_6	A_5	A_4	A_3	A_2	A_1	A_0		
0	1		0	0	0	0	0	0	0	A_8		
0	0	10	0	0	0	1	0	0	0	0	Deep Sleep mode	Deep Sleep mode Control: A[1:0] : Description 00 Normal Mode [POR] 01 Enter Deep Sleep Mode 1 11 Enter Deep Sleep Mode 2 After this command initiated, the chip will enter Deep Sleep Mode, BUSY pad will keep output high.此命令启动后，芯片将进入深度睡眠模式，、BUSY pad 将保持输出高电平。 Remark: To Exit Deep Sleep mode, User required to send HWRESET to the driver 要退出深度睡眠模式，用户需要向驱动程序发送 HWRESET
0	1		0	0	0	0	0	0	A_1	A_0		
0	0	11	0	0	0	1	0	0	0	1	Data Entry mode setting	Define data entry sequence A[2:0] = 011 [POR] A [1:0] = ID[1:0] Address automatic increment / decrement setting The setting of incrementing or decrementing of the address counter can be made independently in each upper and lower bit of the address. 00 –Y decrement, X decrement, 01 –Y decrement, X increment, 10 –Y increment, X decrement, 11 –Y increment, X increment [POR] A[2] = AM Set the direction in which the address counter is updated automatically after data are written to the RAM. AM= 0, the address counter is updated in the X direction. [POR] AM = 1, the address counter is updated in the Y direction.
0	1		0	0	0	0	0	A_2	A_1	A_0		
0	0	12	0	0	0	1	0	0	1	0	SW RESET	It resets the commands and parameters to their S/W Reset default values except R10h-Deep Sleep Mode During operation, BUSY pad will output high. Note: RAM are unaffected by this command.

Command Table

R/W#	D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description
0	0	14	0	0	0	1	0	1	0	0	HV Ready Detection	HV ready detection The command required CLKEN=1 and ANALOGEN=1 Refer to Register 0x22 for detail. After this command initiated, HV Ready detection starts. BUSY pad will output high during detection. The detection result can be read from the Status Bit Read (Command 0x2F).
0	0	15	0	0	0	1	0	1	0	1	VCI Detection	VCI Detection A[2:0] = 100 [POR] , Detect level at 2.3V A[2:0] : VCI level Detect A[2:0] = 011 → 2.2V; 100 → 2.3V; 101 → 2.4V; 110 → 2.5V; 111 → 2.6V; Other → NA The command required CLKEN=1 and ANALOGEN=1 Refer to Register 0x22 for detail. After this command initiated, VCI detection starts. BUSY pad will output high during detection. The detection result can be read from the Status Bit Read (Command 0x2F).
0	1		0	0	0	0	0	A_2	A_1	A_0		

Command Table

R/W#	D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description
0	0	18	0	0	0	1	1	0	0	0	Temperature Sensor Control	Temperature Sensor Selection A[7:0] = 48h [POR], external temperatrure sensor A[7:0] = 80h Internal temperature sensor 内部温度传感器
0	1		A_7	A_6	A_5	A_4	A_3	A_2	A_1	A_0		
0	0	1A	0	0	0	1	1	0	1	0	Temperature Sensor Control (Write to temperature register)	Write to temperature register. A[11:0] = 7FFh [POR]
0	1		A_{11}	A_{10}	A_9	A_8	A_7	A_6	A_5	A_4		
0	1		A_3	A_2	A_1	A_0	0	0	0	0		
0	0	1B	0	0	0	1	1	0	1	1	Temperature Sensor Control (Read from temperature register)	Read from temperature register.
1	1		A_{11}	A_{10}	A_9	A_8	A_7	A_6	A_5	A_4		
1	1		A_3	A_2	A_1	A_0	0	0	0	0		
0	0	1C	0	0	0	1	1	1	0	0	Temperature Sensor Control (Write Command to External temperature sensor)	Write Command to External temperature sensor. A[7:0] = 00h [POR], B[7:0] = 00h [POR], C[7:0] = 00h [POR], A[7:6] A[7:6] – Select no of byte to be sent 00 – Address + pointer 01 – Address + pointer + 1st parameter 10 – Address + pointer + 1st parameter + 2nd pointer 11 – Address A[5:0] – Pointer Setting B[7:0] – 1st parameter C[7:0] – 2nd parameter The command required CLKEN=1. Refer to Register 0x22 for detail. After this command initiated, Write Command to external temperature sensor starts. BUSY pad will output high during operation.
0	1		A_7	A_6	A_5	A_4	A_3	A_2	A_1	A_0		
0	1		B_7	B_6	B_5	B_4	B_3	B_2	B_1	B_0		
0	1		C_7	C_6	C_5	C_4	C_3	C_2	C_1	C_0		

Command Table

R/W#	D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description
0	0	20	0	0	1	0	0	0	0	0	Master Activation	Activate Display Update Sequence 激活显示更新序列 The Display Update Sequence Option is located at R22h. 显示更新顺序选项位于 R22h。 BUSY pad will output high during operation. User should not interrupt this operation to avoid corruption of panel images. BUSY 在操作期间将输出高电平。 用户不应中断此操作以避免面板图像损坏。
0	0	21	0	0	1	0	0	0	0	1	Display Update Control 1	RAM content option for Display Update A[7:0] = 00h [POR] 显示更新的 RAM 内容选项 A[7:4] Red RAM option 0000 Normal 0100 Bypass RAM content as 0 1000 Inverse RAM content A[3:0] BW RAM option 0000 Normal 0100 Bypass RAM content as 0 1000 Inverse RAM content
0	1		A_7	A_6	A_5	A_4	A_3	A_2	A_1	A_0		

Command Table

R/W#	D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description 显示更新序列选项：启用主激活阶段
0	0	22	0	0	1	0	0	0	1	0	Display Update Control 2	Display Update Sequence Option: Enable the stage for Master Activation A[7:0]= FFh (POR)

	Parameter (in Hex)
Enable Clock Signal, Then Enable ANALOG Then DISPLAY with DISPLAY Mode 1 Then Disable ANALOG Then Disable OSC	C7
Enable Clock Signal, Then Enable ANALOG Then DISPLAY with DISPLAY Mode 2 Then Disable ANALOG Then Disable OSC	CF
Enable Clock Signal, Then Load LUT with DISPLAY Mode 1	90
Enable Clock Signal, Then Load Temperature value from I2C Single Master Interface Then Load LUT with DISPLAY Mode 1	B0
Enable Clock Signal, Then Load LUT with DISPLAY Mode 2	98
Enable Clock Signal, Then Load Temperature value from I2C Single Master Interface Then Load LUT with DISPLAY Mode 2	B8
Enable Clock Signal, Then Load LUT with DISPLAY Mode 1 To Disable Clock Signal	91
Enable Clock Signal, Then Load Temperature value from I2C Single Master Interface Then Load LUT with DISPLAY Mode 1 To Disable Clock Signal	B1
Enable Clock Signal, Then Load LUT with DISPLAY Mode 2 To Disable Clock Signal	99
Enable Clock Signal, Then Load Temperature value from I2C Single Master Interface Then Load LUT with DISPLAY Mode 2 To Disable Clock Signal	B9
Enable ANALOG Then DISPLAY with DISPLAY Mode 1 Then Disable ANALOG Then Disable OSC	47
Enable ANALOG Then DISPLAY with DISPLAY Mode 2 Then Disable ANALOG Then Disable OSC	4F
To Enable Clock Signal (CLKEN=1)	80
To Enable Clock Signal, then Enable ANALOG (CLKEN=1, ANALOGEN=1)	C0
Enable ANALOG Then DISPLAY with DISPLAY Mode 1	44
Enable ANALOG Then DISPLAY with DISPLAY Mode 2	4C
To DISPLAY with DISPLAY Mode 1	04
To DISPLAY with DISPLAY Mode 2	0C
To Disable ANALOG, then Disable Clock Signal (CLKEN=0, ANALOGEN=0)	03
To Disable Clock Signal (CLKEN=0)	01

Command Table												
R/W#	D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description
0	0	24	0	0	1	0	0	1	0	0	Write RAM (BW)	After this command, data entries will be written into the BW RAM until another command is written. Address pointers will advance accordingly For Write pixel: Content of Write RAM(BW) = 1 For Black pixel: Content of Write RAM(BW) = 0
0	0	26	0	0	1	0	0	1	1	0	Write RAM (RED)	After this command, data entries will be written into the RED RAM until another command is written. Address pointers will advance accordingly. For Red pixel: Content of Write RAM(RED) = 1 For non-Red pixel [Black or White]: Content of Write RAM(RED) = 0
0	0	27	0	0	1	0	0	1	1	1	Read RAM	After this command, data read on the MCU bus will fetch data from RAM [According to parameter of Register 41h to select reading RAM(BW) / RAM(RED)], until another command is written. Address pointers will advance accordingly. The 1st byte of data read is dummy data.
0	0	28	0	0	1	0	1	0	0	0	VCOM Sense	Enter VCOM sensing conditions and hold for duration defined in 29h before reading VCOM value. The sensed VCOM voltage is stored in register The command required CLKEN=1 and ANALOGEN=1 Refer to Register 0x22 for detail. BUSY pad will output high during operation.
0	0	29	0	0	1	0	1	0	0	1	VCOM Sense Duration	Stabling time between entering VCOM sensing mode and reading acquired. A[6]=1, Normal Mode A[6]=0, Reserve A[3:0] = 09h, duration = 10s. VCOM sense duration = Setting + 1 Seconds
0	1		A_7	A_6	A_5	A_4	A_3	A_2	A_1	A_0		
0	0	2A	0	0	1	0	1	0	1	0	Program VCOM OTP	Program VCOM register into OTP The command required CLKEN=1. Refer to Register 0x22 for detail. BUSY pad will output high during operation.

Command Table

R/W#	D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description
0	0	2C	0	0	1	0	1	1	0	0	Write VCOM register	Write VCOM register from MCU interface A[7:0] = 00h [POR]
0	1		A_7	A_6	A_5	A_4	A_3	A_2	A_1	A_0		

A[7:0]	VCOM	A[7:0]	VCOM
08h	-0.2	44h	-1.7
0Ch	-0.3	48h	-1.8
10h	-0.4	4Ch	-1.9
14h	-0.5	50h	-2
18h	-0.6	54h	-2.1
1Ch	-0.7	58h	-2.2
20h	-0.8	5Ch	-2.3
24h	-0.9	60h	-2.4
28h	-1	64h	-2.5
2Ch	-1.1	68h	-2.6
30h	-1.2	6Ch	-2.7
34h	-1.3	70h	-2.8
38h	-1.4	74h	-2.9
3Ch	-1.5	78h	-3
40h	-1.6	Other	NA

0	0	2D	0	0	1	0	1	1	0	1	OTP Register Read for Display Option	Read Register stored in OTP for Display Option: 1. A[7:0]: VCOM OTP Selection (R37, Byte A) 2. B[7:0]: VCOM Register (R2C) 3. C[7:0]~F[7:0]: Display Mode (R37, Byte B and Byte E) [4 bytes] 4. G[7:0]~H[7:0]: Waveform Version (R37, Byte F and Byte G) [2 bytes]
1	1		A_7	A_6	A_5	A_4	A_3	A_2	A_1	A_0		
1	1		B_7	B_6	B_5	B_4	B_3	B_2	B_1	B_0		
1	1		C_7	C_6	C_5	C_4	C_3	C_2	C_1	C_0		
1	1		D_7	D_6	D_5	D_4	D_3	D_2	D_1	D_0		
1	1		E_7	E_6	E_5	E_4	E_3	E_2	E_1	E_0		
1	1		F_7	F_6	F_5	F_4	F_3	F_2	F_1	F_0		
1	1		G_7	G_6	G_5	G_4	G_3	G_2	G_1	G_0		
1	1		H_7	H_6	H_5	H_4	H_3	H_2	H_1	H_0		

0	0	2E	0	0	1	0	1	1	1	0	User ID Read	Read 10 Byte User ID stored in OTP: A[7:0]]~J[7:0]: UserID (R38, Byte A and Byte J) [10 bytes]
1	1		A_7	A_6	A_5	A_4	A_3	A_2	A_1	A_0		
1	1		B_7	B_6	B_5	B_4	B_3	B_2	B_1	B_0		
1	1		C_7	C_6	C_5	C_4	C_3	C_2	C_1	C_0		
1	1		D_7	D_6	D_5	D_4	D_3	D_2	D_1	D_0		
1	1		E_7	E_6	E_5	E_4	E_3	E_2	E_1	E_0		
1	1		F_7	F_6	F_5	F_4	F_3	F_2	F_1	F_0		
1	1		G_7	G_6	G_5	G_4	G_3	G_2	G_1	G_0		
1	1		H_7	H_6	H_5	H_4	H_3	H_2	H_1	H_0		
1	1		I_7	I_6	I_5	I_4	I_3	I_2	I_1	I_0		
1	1		J_7	J_6	J_5	J_4	J_3	J_2	J_1	J_0		

Command Table

R/W #	D/C #	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description
0	0	2F	0	0	1	0	1	1	1	1	Status Bit Read	Read IC status Bit [POR 0x21] A[5]: HV Ready Detection flag [POR=1] 0: Ready 1: Not Ready A[4]: VCI Detection flag [POR=0] 0: Normal 1: VCI lower than the Detect level A[3]: [POR=0] A[2]: Busy flag [POR=0] 0: Normal 1: BUSY A[1:0]: Chip ID [POR=01] Remark: A[5] and A[4] status are not valid after RESET, they need to be initiated by command 0x14 and command 0x15 respectively.
1	1		0	0	A_5	A_4	0	0	A_1	A_0		
0	0	30	0	0	1	1	0	0	0	0	Program WS OTP	Program OTP of Waveform Setting The contents should be written into RAM before sending this command. The command required CLKEN=1. Refer to Register 0x22 for detail. BUSY pad will output high during operation.
0	0	31	0	0	1	1	0	0	0	1	Load WS OTP	Load OTP of Waveform Setting The command required CLKEN=1. Refer to Register 0x22 for detail. BUSY pad will output high during operation.
0	0	32	0	0	1	1	0	0	1	0	Write LUT register	Write LUT register from MCU interface [70 bytes], which contains the content of VS [nX-LUT], TP #[nX], RP#[n]). Refer to Session 6.7 Waveform Setting
0	1		A_7	A_6	A_5	A_4	A_3	A_2	A_1	A_0		
0	1		B_7	B_6	B_5	B_4	B_3	B_2	B_1	B_0		
0	1		:	:	:	:	:	:	:	:		
0	1		.	..	.	.	.	.	.	.		
0	0	34	0	0	1	1	0	1	0	0	CRC calculation	CRC calculation command BUSY pad will output high during operation.
0	0	35	0	0	1	1	0	1	0	1	CRC Status Read	CRC Status Read A[15:0] is the CRC read out value
1	1		A_{15}	A_{14}	A_{13}	A_{12}	A_{11}	A_{10}	A_9	A_8		
1	1		A_7	A_6	A_5	A_4	A_3	A_2	A_1	A_0		

Command Table												
R/W #	**D/C #**	**Hex**	**D7**	**D6**	**D5**	**D4**	**D3**	**D2**	**D1**	**D0**	**Command**	**Description**
0	0	36	0	0	1	1	0	1	1	0	Program OTP selection	Program OTP Selection according to the OTP Selection Control [R37h and R38h] The command required CLKEN=1. Refer to Register 0x22 for detail. BUSY pad will output high during operation.
0	0	37	0	0	1	1	0	1	1	1	Write OTP selection	Write the OTP Selection: A[7]=1 spare VCOM OTP selection B[7:0]~E[7:0] reserved F[7:0]~G[7:0] module ID /waveform version.
0	1		A_7	0	0	0	0	0	0	0		
0	1		B_7	B_6	B_5	B_4	B_3	B_2	B_1	B_0		
0	1		C_7	C_6	C_5	C_4	C_3	C_2	C_1	C_0		
0	1		D_7	D_6	D_5	D_4	D_3	D_2	D_1	D_0		
0	1		E_7	E_6	E_5	E_4	E_3	E_2	E_1	E_0		
0	1		F_7	F_6	F_5	F_4	F_3	F_2	F_1	F_0		
0	1		G_7	G_6	G_5	G_4	G_3	G_2	G_1	G_0		
1	0	38	0	0	1	1	1	0	0	0	Write Register for User ID	Write Register for User ID A[7:0]]~J[7:0]: UserID [10 bytes]
1	1		A_7	A_6	A_5	A_4	A_3	A_2	A_1	A_0		
1	1		B_7	B_6	B_5	B_4	B_3	B_2	B_1	B_0		
1	1		C_7	C_6	C_5	C_4	C_3	C_2	C_1	C_0		
1	1		D_7	D_6	D_5	D_4	D_3	D_2	D_1	D_0		
1	1		E_7	E_6	E_5	E_4	E_3	E_2	E_1	E_0		
1	1		F_7	F_6	F_5	F_4	F_3	F_2	F_1	F_0		
1	1		G_7	G_6	G_5	G_4	G_3	G_2	G_1	G_0		
1	1		H_7	H_6	H_5	H_4	H_3	H_2	H_1	H_0		
1	1		I_7	I_6	I_5	I_4	I_3	I_2	I_1	I_0		
1	1		J_7	J_6	J_5	J_4	J_3	J_2	J_1	J_0		
0	0	39	0	0	1	1	1	0	0	1	OTP program mode	OTP program mode A[1:0] = 00: Normal Mode [POR] A[1:0] = 11: Internal generated OTP programming voltage Remark: User is required to EXACTLY follow the reference code sequences

Command Table

R/W #	D/C #	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description
0	0	3A	0	0	1	1	1	0	1	0	Set dummy line period	Set number of dummy line period A[6:0] = 2Ch [POR] Available setting 0 to 127.
0	1		0	A_6	A_5	A_4	A_3	A_2	A_1	A_0		
0	0	3B	0	0	1	1	1	0	1	1	Set Gate line width	Set Gate line width (TGate) A[3:0] = 1010 [POR] Remark: Default value will give 50Hz Frame frequency under 44 dummy line pulse setting. 备注：在 44 虚拟线脉冲设置下，默认值将给出 50Hz 帧频率。
0	1		0	0	0	0	A_3	A_2	A_1	A_0		

Resolution: 400x300

Frame Frequency [Hz]	Parameter of 0x3A	Parameter of 0x3B
15	0x79	0x0E
20	0x10	0x0E
25	0x26	0x0D
30	0x4E	0x0C
35	0x18	0x0C
40	0x43	0x0B
45	0x1A	0x0B
50	0x2C	0x0A
55	0x0D	0x0A
60	0x21	0x09
65	0x07	0x09
70	0x28	0x08
75	0x11	0x08
80	0x2F	0x07
85	0x1A	0x07
90	0x08	0x07
95	0x32	0x06
100	0x21	0x06
105	0x11	0x06
110	0x03	0x06
115	0x22	0x05
120	0x14	0x05
125	0x07	0x05
135	0x24	0x04
140	0x18	0x04
145	0x0D	0x04
150	0x03	0x04
155	0x27	0x03
160	0x1C	0x03
165	0x12	0x03
170	0x09	0x03
175	0x00	0x03
180	0x2F	0x02
185	0x25	0x02
190	0x1C	0x02
195	0x14	0x02
200	0x0C	0x02

Remark: Frame rate setting depends on resolution. 帧率设置取决于分辨率。

Command Table

R/W#	D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description 选择 VBD 的边界波形
0	0	3C	0	0	1	1	1	1	0	0	Border Waveform Control 边界波形控制	Select border waveform for VBD A[7:0] = C0h [POR], set VBD as HIZ. A [7:6] :Select VBD option A[7:6] — Select VBD as 00 — GS Transition, Defined in A[1:0] 01 — Fix Level, Defined in A[5:4] 10 — VCOM 11[POR] — HiZ A [5:4] Fix Level Setting for VBD A[5:4] — VBD level 00[POR] — VSS 01 — VSH1 10 — VSL 11 — VSH2 VBD 的 GS 转换设置 A [1:0] GS Transition setting for VBD A[1:0] — VBD Transition 00[POR] — LUT0 01 — LUT1 10 — LUT2 11 — LUT3
0	1		A_7	A_6	A_5	A_4	0	0	A_1	A_0		
0	0	41	0	1	0	0	0	0	0	1	Read RAM Option	Read RAM Option A[0]= 0 [POR] 0 : Read RAM corresponding to 24h 1 : Read RAM corresponding to 26h
0	1		0	0	0	0	0	0	0	A_0		
0	0	44	0	1	0	0	0	1	0	0	Set RAM X - address Start / End position	Specify the start/end positions of the window address in the X direction by an address unit for RAM A[5:0]: XSA[5:0], XStart, 00h [POR] B[5:0]: XEA[5:0], XEnd, 31h [POR]
0	1		0	0	A_5	A_4	A_3	A_2	A_1	A_0		
0	1		0	0	B_5	B_4	B_3	B_2	B_1	B_0		
0	0	45	0	1	0	0	0	1	0	1	Set Ram Y- address Start / End position	Specify the start/end positions of the window address in the Y direction by an address unit for RAM A[8:0]: YSA[8:0], YStart, 000h [POR] B[8:0]: YEA[8:0], YEnd, 12Bh [POR]
0	1		A_7	A_6	A_5	A_4	A_3	A_2	A_1	A_0		
0	1		0	0	0	0	0	0	0	A_8		
0	1		B_7	B_6	B_5	B_4	B_3	B_2	B_1	B_0		
0	1		0	0	0	0	0	0	0	B_8		

Command Table

<table>
<tr><th>R/W#</th><th>D/C#</th><th>Hex</th><th>D7</th><th>D6</th><th>D5</th><th>D4</th><th>D3</th><th>D2</th><th>D1</th><th>D0</th><th>Command</th><th>Description</th></tr>
<tr><td>0</td><td>0</td><td>46</td><td>0</td><td>1</td><td>0</td><td>0</td><td>0</td><td>1</td><td>1</td><td>0</td><td rowspan="2">Auto Write RED RAM for Regular Pattern</td><td rowspan="2">Auto Write RED RAM for Regular Pattern
A[7:0] = 00h [POR]

A[7]: The 1st step value, POR = 0
A[6:4]: Step Hieght, POR= 000
Step of alter RAM in Y-direction according to Gate
<table><tr><td>A[6:4]</td><td>Height</td><td>A[6:4]</td><td>Height</td></tr><tr><td>000</td><td>8</td><td>100</td><td>128</td></tr><tr><td>001</td><td>16</td><td>101</td><td>256</td></tr><tr><td>010</td><td>32</td><td>110</td><td>300</td></tr><tr><td>011</td><td>64</td><td>111</td><td>NA</td></tr></table>
A[2:0]: Step Width, POR= 000
Step of alter RAM in X-direction according to Source
<table><tr><td>A[2:0]</td><td>Width</td><td>A[2:0]</td><td>Width</td></tr><tr><td>000</td><td>8</td><td>100</td><td>128</td></tr><tr><td>001</td><td>16</td><td>101</td><td>256</td></tr><tr><td>010</td><td>32</td><td>110</td><td>400</td></tr><tr><td>011</td><td>64</td><td>111</td><td>NA</td></tr></table>
BUSY pad will output high during operation.</td></tr>
<tr><td>0</td><td>1</td><td></td><td>A_7</td><td>A_6</td><td>A_5</td><td>A_4</td><td>0</td><td>A_2</td><td>A_1</td><td>A_0</td></tr>
<tr><td colspan="13"></td></tr>
<tr><td>0</td><td>0</td><td>47</td><td>0</td><td>1</td><td>0</td><td>0</td><td>0</td><td>1</td><td>1</td><td>1</td><td rowspan="2">Auto Write B/W RAM for Regular Pattern</td><td rowspan="2">Auto Write B/W RAM for Regular Pattern
A[7:0] = 00h [POR]

A[7]: The 1st step value, POR = 0
A[6:4]: Step Hieght, POR= 000
Step of alter RAM in Y-direction according to Gate
<table><tr><td>A[6:4]</td><td>Height</td><td>A[6:4]</td><td>Height</td></tr><tr><td>000</td><td>8</td><td>100</td><td>128</td></tr><tr><td>001</td><td>16</td><td>101</td><td>256</td></tr><tr><td>010</td><td>32</td><td>110</td><td>300</td></tr><tr><td>011</td><td>64</td><td>111</td><td>NA</td></tr></table>
A[2:0]: Step Width, POR= 000
Step of alter RAM in X-direction according to Source
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During operation, BUSY pad will output high.</td></tr>
<tr><td>0</td><td>1</td><td></td><td>A_7</td><td>A_6</td><td>A_5</td><td>A_4</td><td>0</td><td>A_2</td><td>A_1</td><td>A_0</td></tr>
</table>

Command Table												
R/W#	**D/C#**	**Hex**	**D7**	**D6**	**D5**	**D4**	**D3**	**D2**	**D1**	**D0**	**Command**	**Description**
0	0	4E	0	1	0	0	1	1	1	0	Set RAM X address counter	Make initial settings for the RAM X address in the address counter (AC) A[5:0]: 00h [POR].
0	1		0	0	A_5	A_4	A_3	A_2	A_1	A_0		
0	0	4F	0	1	0	0	1	1	1	1	Set RAM Y address counter	Make initial settings for the RAM Y address in the address counter (AC) A[8:0]: 000h [POR].
0	1		A7	A6	A5	A4	A3	A2	A1	A0		
0	1		0	0	0	0	0	0	0	A8		
0	1	74	0	1	1	1	0	1	0	0	Set Analog Block Control 设置模拟块控制	A[7:0]: 54h
0	1		A7	A6	A5	A4	A3	A2	A1	A0		
0	1	7E	0	1	1	1	1	1	1	0	Set Digital Block Control 设置数字块控制	A[7:0]: 3Bh
0	1		A7	A6	A5	A4	A3	A2	A1	A0		
0	1	7F	0	1	1	1	1	1	1	1	NOP	This command is an empty command; it does not have any effect on the display module. However it can be used to terminate Frame Memory Write or Read Commands.

8 COMMAND DESCRIPTION

8.1 Driver Output Control (01h)

此三字节命令有多种配置，每个位设置描述如下：

This triple byte command has multiple configurations and each bit setting is described as follows:

R/W	DC	IB7	IB6	IB5	IB4	IB3	IB2	IB1	IB0
W	1	MUX7	MUX6	MUX5	MUX4	MUX3	MUX2	MUX1	MUX0
POR		0	0	1	1	1	1	1	1
W	1								MUX8
POR									1
W	1						GD	SM	TB
POR							0	0	0

指定驱动器的线数：MUX[8:0] + 1。复用比（MUX ratio）从 16 MUX 到 300MUX。

MUX[8:0]: Specify number of lines for the driver: MUX[8:0] + 1. Multiplex ratio (MUX ratio) from 16 MUX to 300MUX.

GD: Selects the 1st output Gate 选择第一个输出门 该位与面板上的 GATE 布局连接相匹配。 它定义了第一条扫描线。
This bit is made to match the GATE layout connection on the panel. It defines the first scanning line.

SM: Change scanning order of gate driver. 更改栅极驱动器的扫描顺序。
When SM is set to 0, left and right interlaced is performed. 当 SM 设置为 0 时，执行左右隔行扫描。
When SM is set to 1, no splitting odd / even of the GATE signal is performed, 当 SM 设置为 1 时，不执行 GATE 信号的奇/偶分割，
Output pin assignment sequence is shown as below (for 300 MUX ratio):
输出引脚分配顺序如下所示（对于 300 MUX 比率）：

	SM=0	SM=0	SM=1	SM=1
Driver	GD=0	GD=1	GD=0	GD=1
G0	ROW0	ROW1	ROW0	ROW150
G1	ROW1	ROW0	ROW150	ROW0
G2	ROW2	ROW3	ROW1	ROW151
G3	ROW3	ROW2	ROW151	ROW1
:	:	:	:	:
G148	ROW148	ROW149	ROW74	ROW224
G149	ROW149	ROW148	ROW224	ROW74
G150	ROW150	ROW151	ROW75	ROW225
G151	ROW151	ROW150	ROW225	ROW75
:	:	:	:	:
G296	ROW296	ROW297	ROW148	ROW298
G297	ROW297	ROW296	ROW298	ROW148
G298	ROW298	ROW299	ROW149	ROW299
G299	ROW299	ROW298	ROW299	ROW149

See “Scan Mode Setting” on next page.

TB: Change scanning direction of gate driver. 改变栅极驱动器的扫描方向。
This bit defines the scanning direction of the gate for flexible layout of signals in module either from up to down (TB = 0) or from bottom to up (TB = 1).
该位定义门的扫描方向，以便灵活地在模块中从上到下（TB = 0）或从下到上（TB = 1）布局信号。

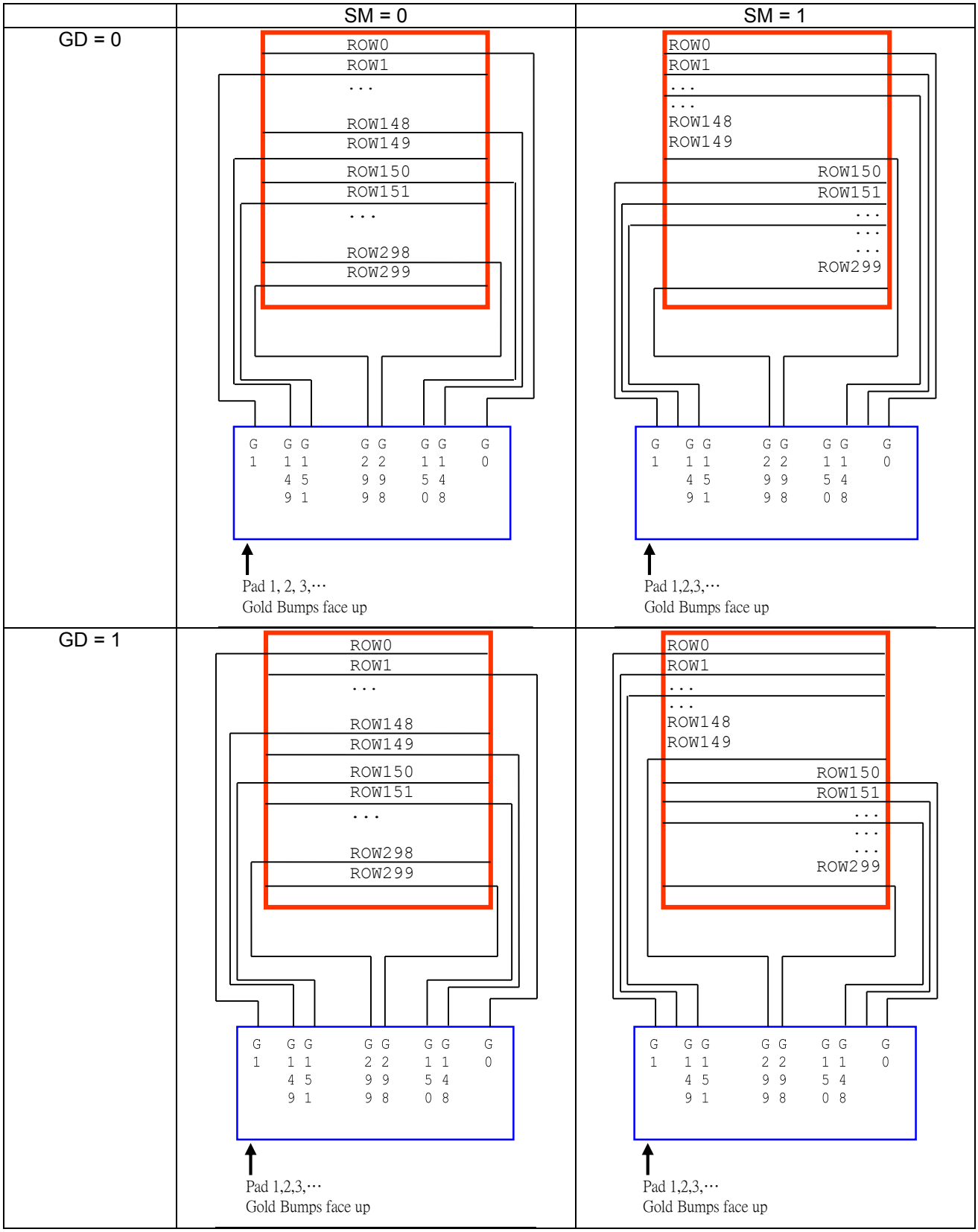


Figure 8-1: Output pin assignment on different Scan Mode Setting

8.2 Gate Scan Start Position (0Fh)

R/W	DC	IB7	IB6	IB5	IB4	IB3	IB2	IB1	IB0
W	1	SCN7	SCN6	SCN5	SCN4	SCN3	SCN2	SCN1	SCN0
POR		0	0	0	0	0	0	0	0
W	1	0	0	0	0	0	0	0	SCN8
POR		0	0	0	0	0	0	0	0

此命令用于设置 Gate Start Position，通过选择 0 到 299 之间的值来确定显示 RAM 的起始门。

This command is to set Gate Start Position for determining the starting gate of display RAM by selecting a value from 0 to 299. Figure 8-2 shows an example using this command of this command when MUX ratio= 300 and MUX ratio= 150 “ROW” means the graphic display data RAM row.

图 8-2 显示了在 MUX ratio=300 和 MUX ratio=150 时使用该命令的示例 “ ROW ”表示图形显示数据 RAM 行。

Figure 8-2: Example of Set Display Start Line with no Remapping

	MUX ratio (01h) = 12Bh	MUX ratio (01h) = 095h	MUX ratio (01h) = 095h
GATE Pin	Gate Start Position (0Fh) = 000h	Gate Start Position (0Fh) = 000h	Gate Start Position (0Fh) = 04Bh
G0	ROW0	ROW0	-
G1	ROW1	ROW1	-
G2	ROW2	ROW2	-
G3	ROW3	ROW3	-
:	:	:	:
:	:	:	:
G73	:	:	-
G74	:	:	-
G75	:	:	ROW75
G76	:	:	ROW76
:	:	:	:
:	:	:	:
G148	ROW148	ROW148	:
G149	ROW149	ROW149	:
G150	ROW150	-	:
G151	ROW151	-	:
:	:	:	:
	:	:	:
G223	:	:	ROW223
G224	:	:	ROW224
G225	:	:	-
G226	:	:	-
	:	:	:
:	:	:	:
G296	ROW296	-	-
G297	ROW297	-	-
G298	ROW298	-	-
G299	ROW299	-	-
Display Example			

8.3 Data Entry Mode Setting (11h) 数据输入模式设置

This command has multiple configurations and each bit setting is described as follows:
该命令有多种配置，每个位设置说明如下：

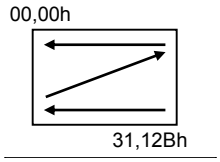
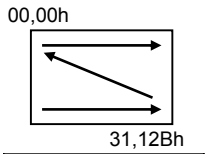
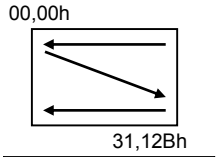
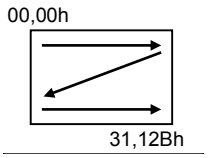
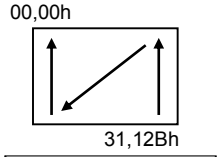
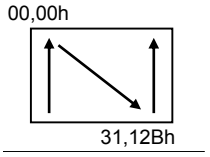
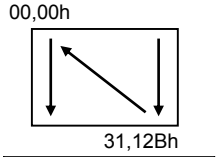
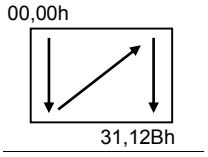
R/W	DC	IB7	IB6	IB5	IB4	IB3	IB2	IB1	IB0
W	1						AM	ID1	ID0
POR		0	0	0	0	0	0	1	1

当 ID[1:0] = “01”时，数据写入 RAM 后，地址计数器自动加 1。 当 ID[1:0] = “00” 时，地址计数器会在数据写入 RAM 后自动减 1。

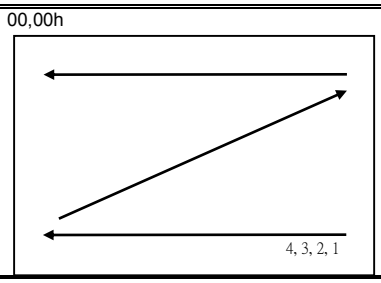
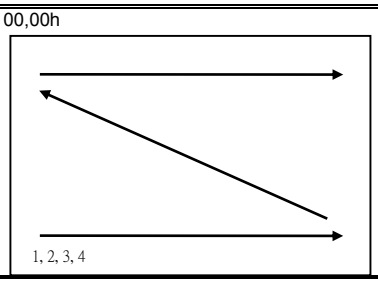
ID[1:0]: The address counter is automatically incremented by 1, after data is written to the RAM when ID[1:0] = “01”. The address counter is automatically decremented by 1, after data is written to the RAM when ID[1:0] = “00”. The setting of incrementing or decrementing of the address counter can be made independently in each upper and lower bit of the address. The direction of the address when data is written to the RAM is set by AM bits.
地址计数器的递增或递减的设置可以在地址的每个高位和低位独立进行。 数据写入 RAM 时的地址方向由 AM 位设置。

AM: Set the direction in which the address counter is updated automatically after data are written to the RAM. When AM = “0”, the address counter is updated in the X direction. When AM = “1”, the address counter is updated in the Y direction. When window addresses are selected, data are written to the RAM area specified by the window addresses in the manner specified with ID[1:0] and AM bits. 设置数据写入 RAM 后地址计数器自动更新的方向。

当 AM = “0”时，地址计数器在 X 方向上更新。
当 AM = “1”时，地址计数器在 Y 方向更新。

	ID [1:0]="00” X: decrement Y: decrement	ID [1:0]="01” X: increment 增加 Y: decrement 减小	ID [1:0]="10” X: decrement Y: increment	ID [1:0]="11” X: increment Y: increment
AM="0” X-mode				
AM="1” Y-mode				

The pixel sequence is defined by the ID [0],

	ID[1:0]="00” X: decrement Y: decrement	ID[1:0]="01” X: increment Y: decrement
AM="0” X-mode		

31,12Bh

8.4 Set RAM X - Address Start / End Position (44h)

R/W	DC	IB7	IB6	IB5	IB4	IB3	IB2	IB1	IB0
W	1			XSA5	XSA4	XSA3	XSA2	XSA1	XSA0
POR		0	0	0	0	0	0	0	0
W	1			XEA5	XEA4	XEA3	XEA2	XEA1	XEA0
POR		0	0	1	1	0	0	0	1

以 8 倍地址单位指定窗口地址在 X 方向的开始/结束位置。数据写入由 XSA [5:0] 和 XEA [5:0] 指定的地址确定的区域内的 RAM

XSA[5:0]/XEA[5:0]: Specify the start/end positions of the window address in the X direction by 8 times address unit. Data is written to the RAM within the area determined by the addresses specified by XSA [5:0] and XEA [5:0]. These addresses must be set before the RAM write. 这些地址必须在 RAM 写入之前设置。

It allows on XEA [5:0] ≤ XSA [5:0]. The settings follow the condition on 00h ≤ XSA [5:0], XEA [5:0] ≤ 31h. The windows is followed by the control setting of Data Entry Setting (R11h)

它允许 XEA [5:0] ≤ XSA [5:0]。 设置遵循 00h ≤ XSA [5:0]、XEA [5:0] ≤ 31h 的条件。 窗口后面是数据输入设置（R11h）的控制设置

8.5 Set RAM Y - Address Start / End Position (45h)

R/W	DC	IB7	IB6	IB5	IB4	IB3	IB2	IB1	IB0
W	1	YSA7	YSA6	YSA5	YSA4	YSA3	YSA2	YSA1	YSA0
POR		0	0	0	0	0	0	0	0
W	1	0	0	0	0	0	0	0	YSA8
POR		0	0	0	0	0	0	0	0
W	1	YEA7	YEA6	YEA5	YEA4	YEA3	YEA2	YEA1	YEA0
POR		0	0	1	0	1	0	1	1
W	1	0	0	0	0	0	0	0	YEA8
POR		0	0	0	0	0	0	0	1

以地址单位指定窗口地址在 Y 方向的开始/结束位置。数据写入由 YSA [8:0] 和 YEA [8:0] 指定的地址确定的区域内的 RAM。这些地址必须在 RAM 写入之前设置。

YSA[8:0]/YEA[8:0]: Specify the start/end positions of the window address in the Y direction by an address unit. Data is written to the RAM within the area determined by the addresses specified by YSA [8:0] and YEA [8:0]. These addresses must be set before the RAM write.

It allows YEA [8:0] ≤ YSA [8:0]. The settings follow the condition on 00h ≤ YSA [8:0], YEA [8:0] ≤ 12Bh. The windows is followed by the control setting of Data Entry Setting (R11h)

它允许 YEA [8:0] ≤ YSA [8:0]。 设置遵循 00h ≤ YSA [8:0]，YEA [8:0] ≤ 12Bh 的条件。 窗口后面是数据输入设置（R11h）的控制设置

8.6 Set RAM Address Counter (4Eh-4Fh)

Reg#	R/W	DC	IB7	IB6	IB5	IB4	IB3	IB2	IB1	IB0
4Eh	W	1			XAD5	XAD4	XAD3	XAD2	XAD1	XAD0
	POR		0	0	0	0	0	0	0	0
4Fh	W	1	YAD7	YAD6	YAD5	YAD4	YAD3	YAD2	YAD1	YAD0
	POR		0	0	0	0	0	0	0	0
	W	1								YAD8
	POR									0

XAD[5:0]: Make initial settings for the RAM X address in the address counter (AC).
YAD[8:0]: Make initial settings for the RAM Y address in the address counter (AC).

After RAM data is written, the address counter is automatically updated according to the settings with AM, ID bits and setting for a new RAM address is not required in the address counter. Therefore, data is written consecutively without setting an address. The address counter is not automatically updated when data is read out from the RAM. RAM address setting cannot be made during the standby mode. The address setting should be made within the area designated with window addresses which is controlled by the Data Entry Setting (R11h) {AM, ID[1:0]} ; RAM Address XStart / XEnd Position (R44h) and RAM Address Ystart /Yend Position (R45h). Otherwise undesirable image will be displayed on the Panel.

9 Typical Operating Sequence

9.1 Normal Display

Sequence	Action by	Command	Action Description	Remark
1	User	-	Power on (VCI supply);	
2	User	-	HW Reset	
	IC		After HW reset, the IC will be ready for command input	
	User	C 12	Command: SW Reset	
	IC		After SW reset, the IC will have Registers load with POR value VCOM register loaded with OTP value IC enter idle mode	BUSY = H
	User	-	Wait until BUSY = L	
.3		-	Send initial code to driver including setting of	
	User	C 74 D 54	Command: Set Analog Block Control	
	User	C 7E D 3B	Command: Set Digital Block Control	
	User	C 01	Command: Driver Output Control (MUX, Source gate scanning direction)	
	User	C 3A	Command: Set dummy line period	
	User	C 3B	Command: Set Gate line width	
	User	C 3C	Command: Border waveform control	
4		-	Data operations for Black White	
	User	C 11	Command: Data Entry mode setting	
	User	C 44	Command: RAM X address start /end position	
	User	C 45	Command: RAM Y address start /end position	
	User	C 4E	Command: RAM X address counter	
	User	C 4F	Command: RAM Y address counter	
	User	C 24	Command: write BW RAM	
			Ram Content for Display	
5		-	Data operations for RED	
	User	C 11	Command: Data Entry mode setting	
	User	C 44	Command: RAM X address start /end position	
	User	C 45	Command: RAM Y address start /end position	
	User	C 4E	Command: RAM X address counter	
	User	C 4F	Command: RAM Y address counter	
	User	C 26	Command: write RED RAM	
			Ram Content for Display	
6	User	C 22	Command: Display Update Control 2	BUSY = H
	User	C 20	Command: Master Activation	
	IC	-	Booster and regulators turn on 升压器和稳压器打开	
	IC	-	Load LUT register with corresponding waveform setting stored in OTP) 使用存储在 OTP 中的相应波形设置加载 LUT 寄存器	
	IC	-	Send output waveform according RAM content and LUT. 根据 RAM 内容和 LUT 发送输出波形。	
	IC	-	Booster and Regulators turn off 增压器和调节器关闭	
	IC	-	Back to idle mode	
	User	-	Wait until BUSY = L	
7	User	-	IC power off;	

9.2 VCOM OTP Program

Sequence	Action by	Command	Action Description	Remark
1	User	-	Power on (VCI and VPP supply)	
2	User	-	HW Reset	
	User	C 12	Command: SW Reset	BUSY = H
	User	-	Wait until BUSY = L	
3	User	C 74 D 54	Command: Set Analog Block Control	
	User	C 7E D 3B	Command: Set Digital Block Control	
	User	C 22 D 80 C 20	Command: Master Activation (assigned by R22h) (Enable clock signal)	BUSY = H
	User	-	Wait until BUSY = L	
4	User	C 37	Proceed OTP sequence. Command: OTP selection Control (default or spare)	OTP selection register
5	User	C 36	Command: Program OTP selection	BUSY = H
	User	-	Wait until BUSY = L	
	User	-	Power OFF (VPP supply)	
6		-	Send initial code to driver including setting of (or leave as POR)	VCOM 感应在应用期间应具有相同的设置 VCOM sensing should have same setting during application
	User	C 01	Command: Driver Output Control (MUX, Source gate scanning direction)	
	User	C 03	Command: Gate Driving voltage Control	
	User	C 04	Command: Source Driving voltage Control	
	User	C 3A	Command: Set dummy line period	
	User	C 3B	Command: Set Gate line width	
	User	C 32	Command: Write LUT register VCOM sense required full set of LUT for operation, USER required writing LUT in register 32h	
		-	LUT parameter	
	User	C 22 D 40 C 20	Command: Master Activation (assigned by R22h) [Enable Analog blocks]	BUSY = H
	User	-	Wait until BUSY = L	
7	User	C 29 D 49	Command: VCOM Sense Duration for 10 seconds VCOM 感应持续时间 10 秒	
8	User	C 28	Command: VCOM sense	BUSY = H
	IC	-	VCOM pin in sensing mode	
	IC	-	All Source cell have VSS output	
			All Gate scanning continuously	
	IC	-	According to R29h	
	IC	-	Detect VCOM voltage and store in register	
	IC	-	All Gate Stop Scanning.	
	User	-	Wait until BUSY = L	
9	User	C 22 D 02 C 20	Command: Master Activation (assigned by R22h) [Disable Analog blocks]	BUSY = H
	User	-	Wait until BUSY = L	
	User	-	Power On (VPP supply)	
10	User	C 2A	Command: Program VCOM OTP	BUSY = H
	User	-	Wait until BUSY = L	
11	User	C 22 D 01 C 20	Command: Display Update Control 2 and Master Activation (Disable clock signal)	BUSY = H
	User	-	Wait until BUSY = L	
12	User	-	IC power off (VCI and VPP Supply)	

9.3 WS OTP Program

Sequence	Action by	Command	Action Description	Remark
1	User	-	Power on (VCI supply)	
2	User	-	Power on (VPP supply)	
3	User	-	HW Reset	
	User	C 12	Command: SW Reset	BUSY = H
	User	-	Wait until BUSY = L	
4	User	C 74 D 54	Command: Set Analog Block Control	
	User	C 7E D 3B	Command: Set Digital Block Control	
	User	C 22 D 80 C 20	Command: Master Activation (assigned by R22h) (Enable clock signal)	BUSY = H
	User	-	Wait BUSY = L	
5	User	C 11 D 03	Command: Data Entry mode setting Set Address automatic increment setting = X increment and Y increment Set Address counter update in X direction	
6	User	C 44 D 00 D 31	Command: RAM X address start /end position Set RAM X address start /end from S0 to S399	
7	User	C 45 D 00 D 00 D 2B D 01	Command: RAM Y address start /end position Set RAM Y address start /end from G0 to G299	
8	User	C 4E D 00	Command: RAM X address counter Set RAM X address counter as 0	
9	User	C 4F D 00 D 00	Command: RAM Y address counter Set RAM Y address counter as 0	
12	User	C 24	Write corresponding data into RAM 将相应数据写入RAM	
			Following specific format 遵循特定格式	
			Write into RAM	
			Full LUT	
13	User	C 4E D 00 C 4F D 00 D 00	Command: RAM address start /end position (Initial Ram address counter)	
14	User	C 30	Command: Program WS OTP Waveform Setting OTP programming	BUSY = H
	User	-	Wait BUSY = L	
15	User	C 22 D 01 C 20	Command: Master Activation (assigned by R22h) [Disable clock signal]	BUSY = H
	User	-	Wait BUSY = L	
16	User	-	Power off VPP and VCI	

10 Absolute Maximum Rating

Table 10-1 : Maximum Ratings

Symbol	Parameter	Rating	Unit
V_{CI}	Logic supply voltage	-0.5 to +4.0	V
V_{IN}	Logic Input voltage	-0.5 to V_{DDIO}+0.5	V
V_{OUT}	Logic Output voltage	-0.5 to V_{DDIO}+0.5	V
T_{OPR}	Operation temperature range	-40 to +85	℃
T_{STG}	Storage temperature range	-65 to +150	℃

Maximum ratings are those values beyond which damages to the device may occur. Functional operation should be restricted to the limits in the Electrical Characteristics tables or Pin Description section

This device contains circuitry to protect the inputs against damage due to high static voltages or electric fields; however, it is advised that normal precautions be taken to avoid application of any voltage higher than maximum rated voltages to this high impedance circuit. For proper operation it is recommended that V_{CI} be constrained to the range $V_{SS} < V_{CI}$. Reliability of operation is enhanced if unused input is connected to an appropriate logic voltage level (e.g., either V_{SS} or V_{DDIO}). Unused outputs must be left open. This device may be light sensitive. Caution should be taken to avoid exposure of this device to any light source during normal operation. This device is not radiation protected.

11 Electrical Characteristics

The following specifications apply for: VSS=0V, VCI=3.0V, VDD=1.8V, T_{OPR}=25ºC.

Table 11-1: DC Characteristics

Symbol	Parameter	Applicable pin	Test Condition	Min.	Typ.	Max.	Unit
V_{CI}	VCI operation voltage	VCI		2.2	3.0	3.7	V
V_{DD}	VDD operation voltage	VDD		1.7	1.8	1.9	V
V_{COM_DC}	VCOM_DC output voltage	VCOM		-3.0		-0.2	V
dV_{COM_DC}	VCOM_DC output voltage deviation	VCOM		-200		200	mV
V_{COM_AC}	VCOM_AC output voltage	VCOM		V_{SL} + V_{COM_DC}	V_{COM_DC}	V_{SH1}+ V_{COM_DC}	V
V_{GATE}	Gate output voltage	G0~G299		-20		+20	V
$V_{GATE(p-p)}$	Gate output peak to peak voltage	G0~G299				40	V
V_{SH1}	Positive Source output voltage	VSH1		+2.4	+15	+17	V
dV_{SH1}	VSH1 output voltage deviation	VSH1	From 2.4V to 8.8V	-100		100	mV
			From 9.0V to 17V	-200		200	mV
V_{SH2}	Positive Source output voltage	VSH2		+2.4	+5	+17	V
dV_{SH2}	VSH2 output voltage deviation	VSH2	From 2.4V to 8.8V	-100		100	mV
			From 9.0V to 17V	-200		200	mV
V_{SL}	Negative Source output voltage	VSL		-17	-15	-9	V
dV_{SL}	VSL output voltage deviation	VSL		-200		200	mV
V_{IH}	High level input voltage	SDA, SCL, CS#, D/C#, RES#, BS[2:1], M/S#, EXTVDD, CL		0.8V_{DDIO}			V
V_{IL}	Low level input voltage					0.2V_{DDIO}	V
V_{OH}	High level output voltage	SDA, BUSY, CL	IOH = -100uA	0.9V_{DDIO}			V
V_{OL}	Low level output voltage		IOL = 100uA			0.1V_{DDIO}	V
V_{PP}	OTP Program voltage	VPP		7.25	7.5	7.75	V

Symbol	Parameter	Applicable pin	Test Condition	Min.	Typ.	Max.	Unit
Islp_VCI	Sleep mode current	VCI	DC/DC OFF No clock No output load MCU interface access Ram data retain		20	35	uA
Idslp_VCI1	Current of deep sleep mode 1	VCI	DC/DC OFF No clock No output load No MCU interface access Retain Ram data but cannot access the RAM.		1	5	uA
Idslp_VCI2	Current of deep sleep mode 2	VCI	DC/DC OFF No clock No output load No MCU interface access Cannot retain RAM data.		0.7	3	uA
Iopr_VCI	Operating Mode current	VCI	VCI=3.0V		1000		uA
V_{GH}	Operating Mode Output Voltage	VGH	Enable Clock and Analog by Master Activation Command VGH=20V VGL=-VGH VSH1=15V VSH2=5V VSL=-15V VCOM = -2V No waveform transitions. No loading. No RAM read/write No OTP read /write	19.5	20	20.5	V
V_{SH1}		VSH1		14.8	15	15.2	V
V_{SH2}		VSH2		4.9	5	5.1	V
V_{SL}		VSL		-15.2	-15	-14.8	V
V_{COM}		VCOM		-2.2	-2	-1.8	V

Table 11-2: Regulators Characteristics

Symbol	Parameter	Test Condition	Applicable pin	Min.	Typ.	Max.	Unit
IVGH	VGH current	VGH = 20V	VGH			200	uA
IVGL	VGL current	VGL = -VGH	VGL			300	uA
IVSH1	VSH1 current	VSH1 = +15V	VSH1			800	uA
IVSH2	VSH2 current	VSH2 = +5V	VSH2			800	uA
IVSL	VSL current	VSL = -15V	VSL			800	uA
IVCOM	VCOM current	VCOM = -2V	VCOM			100	uA

12 AC Characteristics

12.1 Oscillator frequency

The following specifications apply for: VSS=0V, VDD=1.8V, T_{OPR}=25ºC.

Table 12-1: Oscillator Frequency

Symbol	Parameter	Test Condition	Applicable pin	Min.	Typ.	Max.	Unit
Fosc	Internal Oscillator frequency	VCI=2.2 to 3.7V	CL	0.95	1	1.05	MHz

12.2 Serial Peripheral Interface

The following specifications apply for: VDDIO - VSS = 2.2V to 3.7V, $\mathbf{T_{OPR}}$ = 25°C, CL=20pF

Table 12-2 : Serial Peripheral Interface Timing Characteristics

Write mode

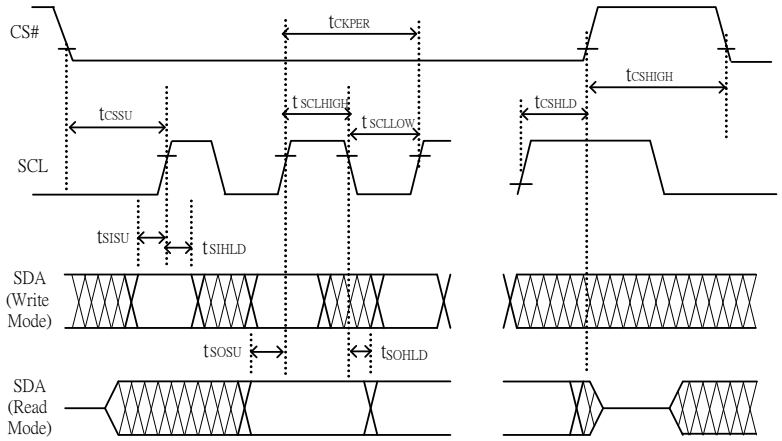
Symbol	Parameter	Min	Typ	Max	Unit
f_{SCL}	SCL frequency (Write Mode)			20	MHz
t_{CSSU}	Time CS# has to be low before the first rising edge of SCLK	20			ns
t_{CSHLD}	Time CS# has to remain low after the last falling edge of SCLK	20			ns
t_{CSHIGH}	Time CS# has to remain high between two transfers	100			ns
$t_{SCLHIGH}$	Part of the clock period where SCL has to remain high	25			ns
t_{SCLLOW}	Part of the clock period where SCL has to remain low	25			ns
t_{SISU}	Time SI (SDA Write Mode) has to be stable before the next rising edge of SCL	10			ns
t_{SIHLD}	Time SI (SDA Write Mode) has to remain stable after the rising edge of SCL	40			ns

Read mode

Symbol	Parameter	Min	Typ	Max	Unit
f_{SCL}	SCL frequency (Read Mode)			2.5	MHz
t_{CSSU}	Time CS# has to be low before the first rising edge of SCLK	100			ns
t_{CSHLD}	Time CS# has to remain low after the last falling edge of SCLK	50			ns
t_{CSHIGH}	Time CS# has to remain high between two transfers	250			ns
$t_{SCLHIGH}$	Part of the clock period where SCL has to remain high	180			ns
t_{SCLLOW}	Part of the clock period where SCL has to remain low	180			ns
t_{SOSU}	Time SO(SDA Read Mode) will be stable before the next rising edge of SCL		50		ns
t_{SOHLD}	Time SO (SDA Read Mode) will remain stable after the falling edge of SCL		0		ns

Note: All timings are based on 20% to 80% of VDDIO-VSS

Figure 12-1: SPI timing diagram



13 Application Circuit

Figure 13-1: Schematic of SSD1619A application circuit

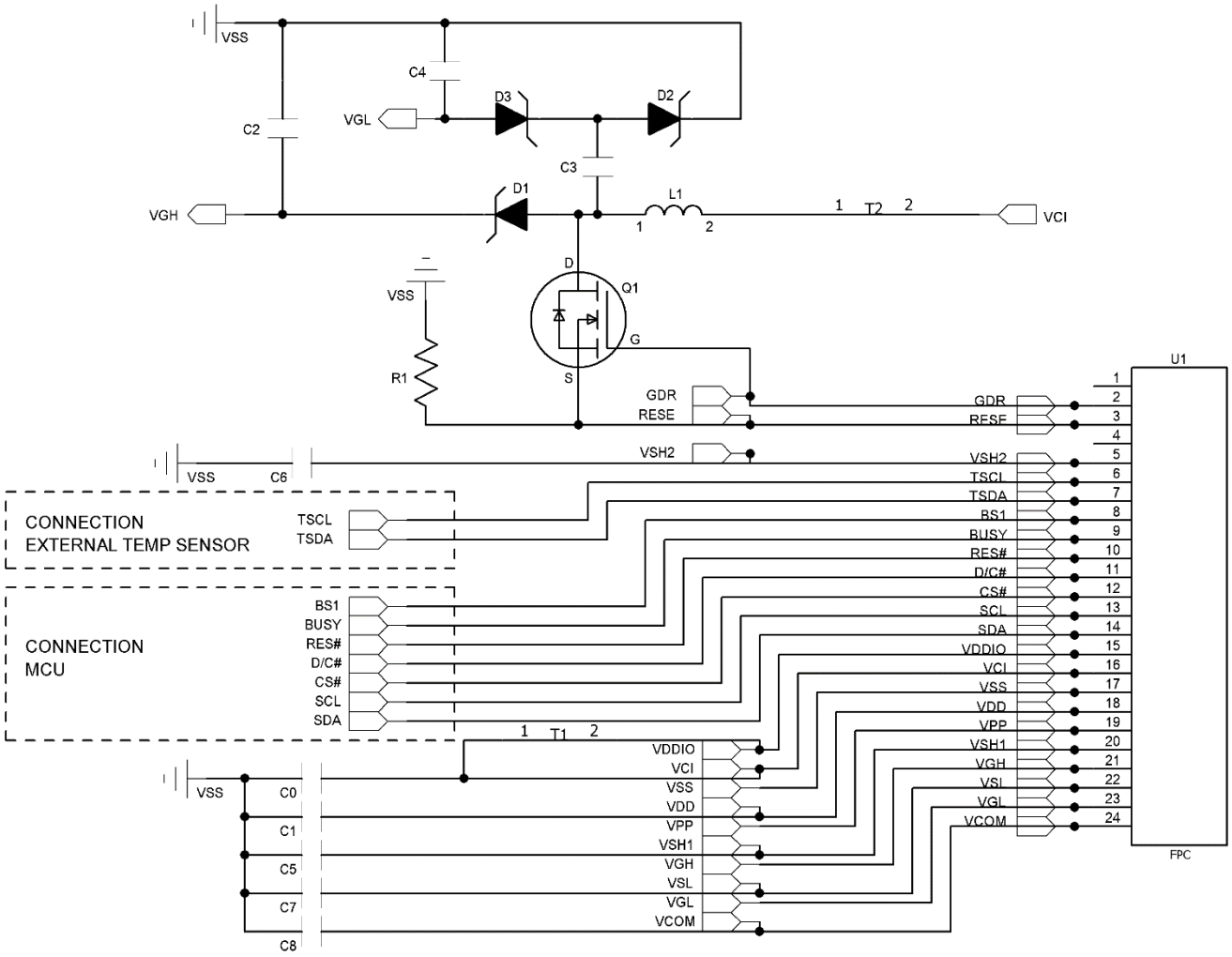
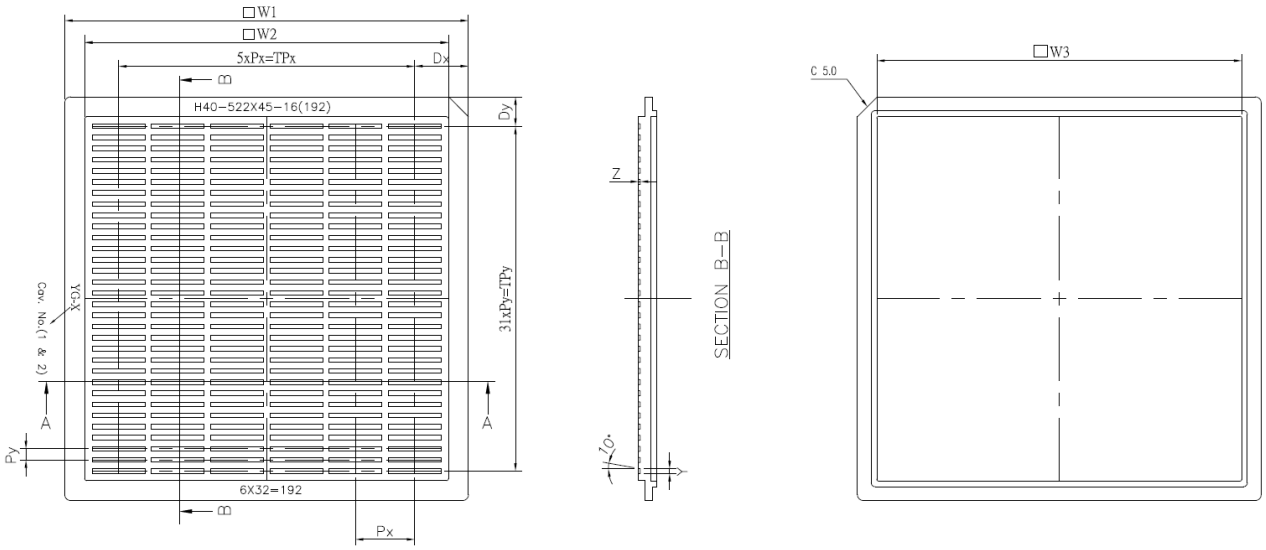


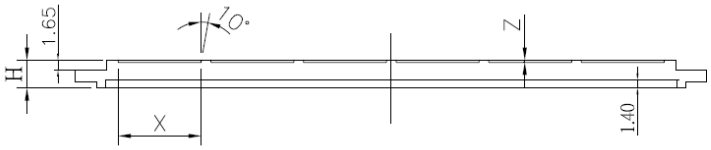
Table 13-1: Component list for SSD1619A application circuit

Part Name	Value / Type	Reference Part
C0-C1	1uF [Max 10V]	TDK: C1005X5R1A105K
C2-C7	1uF [Max 25V]	TDK: C1608X5R1E105K
C8	0.47uF [Max 25V]	TDK: C1608X5R1E474K
D1-D3	Diode	OnSemi: MBR0530
L1	47uH	Sumida: CDRH2D18/LDNP-470NC
Q1	NMOS	Vishay: Si1304BDL
R1	2.2 Ohm	Vishay: CRCW08052R20FKEA
U1	0.5mm ZIF socket	Hirose: FH34S-24S-0.5SH(50)

14 PACKAGE INFORMATION

Figure 14-1 : SSD1619AZ die tray information





SECTION A-A

Symbol	Spec(mm) (mil)
W1	101.60±0.10(4000)
W2	91.55±0.10(3604)
W3	91.85±0.10(3616)
H	4.55±0.10 (179)
Dx	13.55±0.10 (533)
TPx	74.50±0.10(2933)
Dy	7.40±0.10 (291)
TPy	86.80±0.10(3417)
Px	14.90±0.05 (587)
Py	2.80±0.05 (110)
X	13.26±0.05 (522)
Y	1.15±0.05 (45)
Z	0.40±0.05 (16)
N	192(pocket number)

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